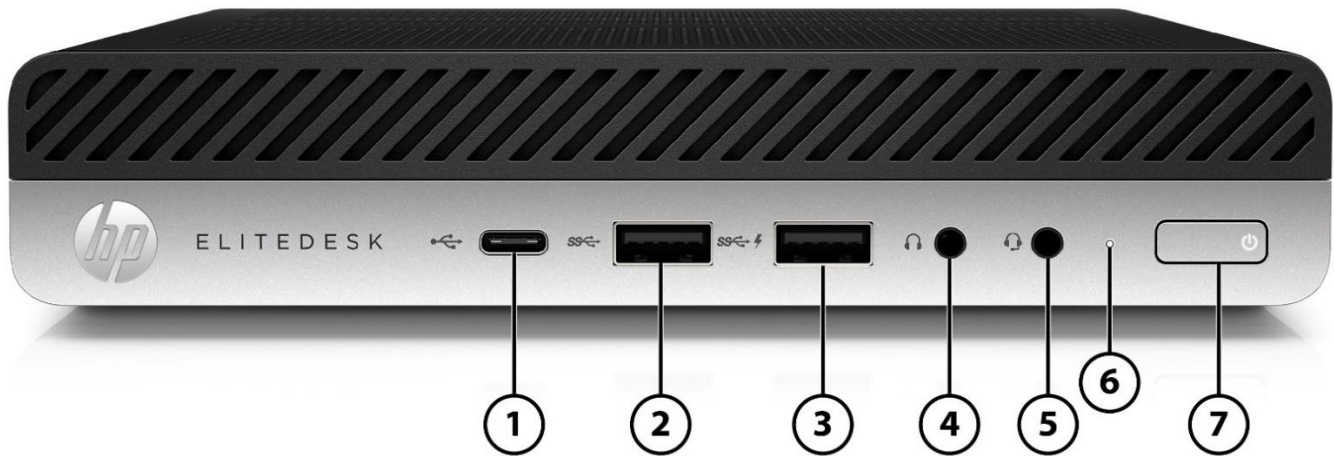


Overview

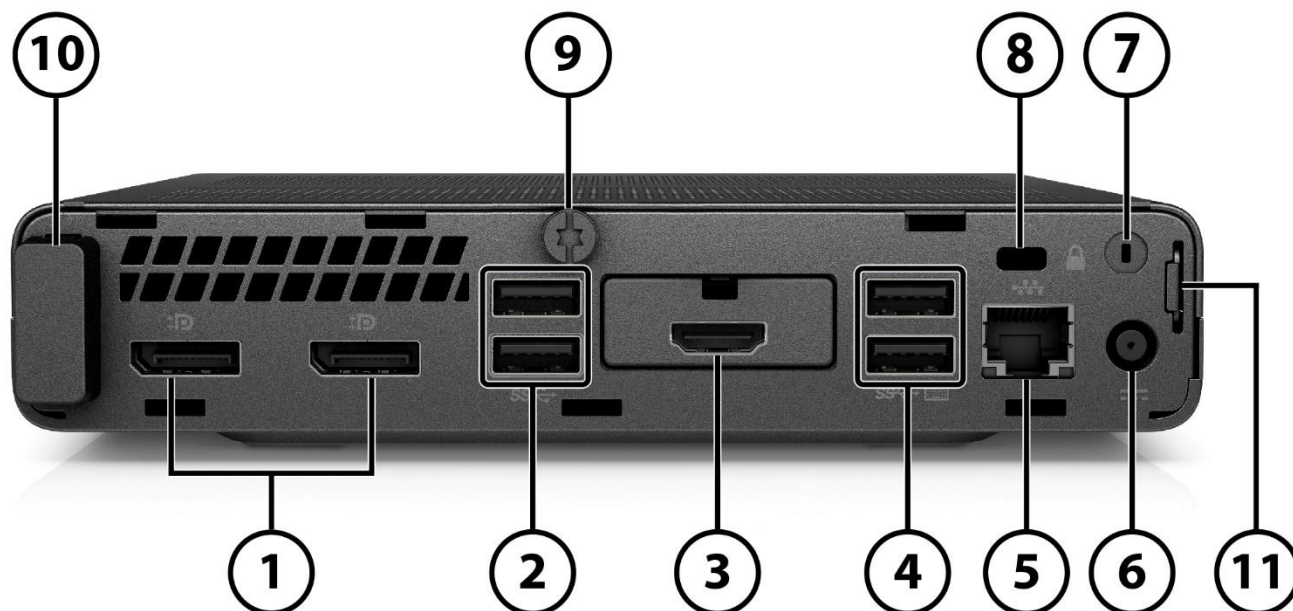
HP EliteDesk 800 G4 Desktop Mini Business PC



- | | |
|--|---|
| 1. USB Type-C™ 3.1 Gen 2 Port (charge support up to 5V/3A) | 5. Universal Audio Jack with CTIA headset support |
| 2. USB 3.1 Gen 2 Type A | 6. Hard Drive activity light |
| 3. USB 3.1 Gen 1 Type A (charge support up to 5V/1.5A) | 7. Dual-state power button |
| 4. Headphone connector | |

Overview

HP EliteDesk 800 G4 Desktop Mini Business PC



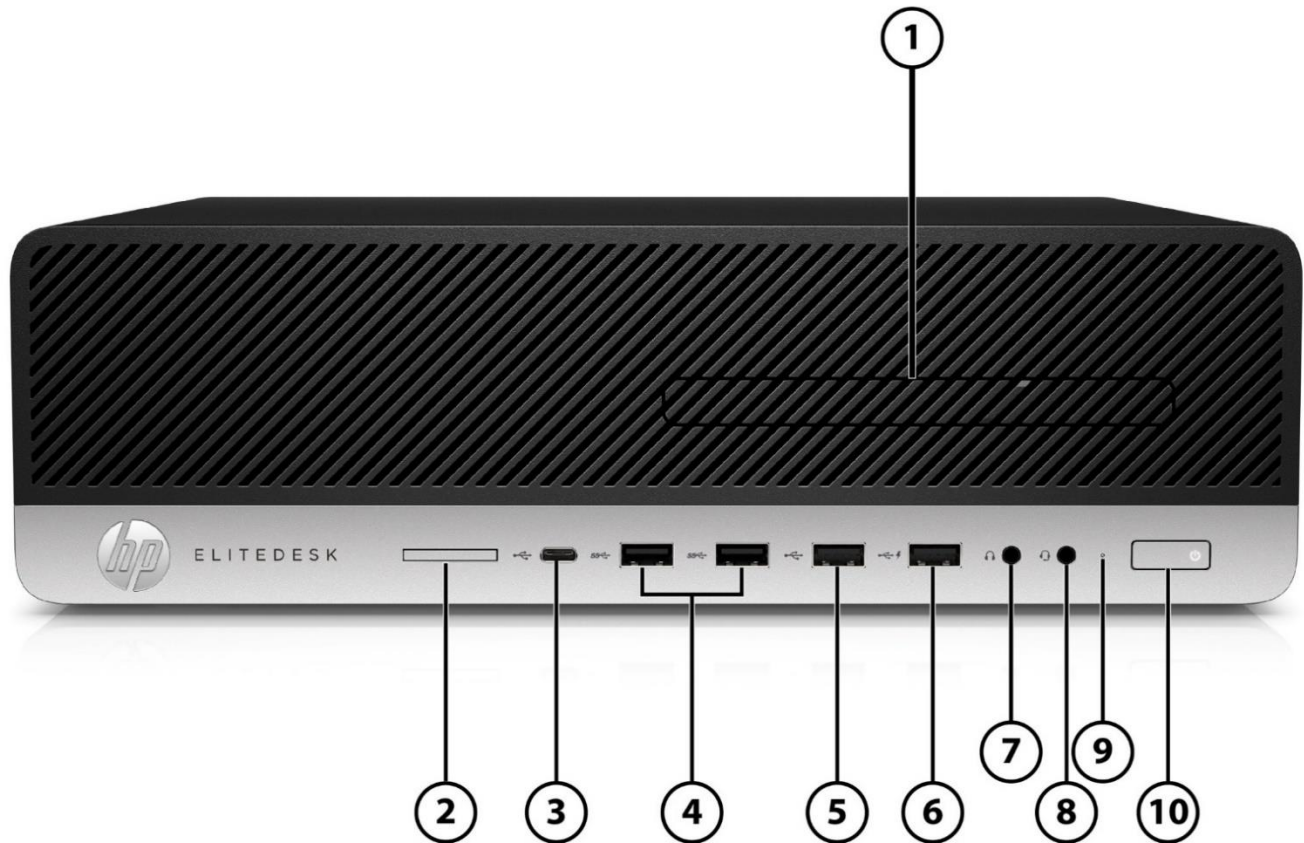
- | | |
|---|-----------------------------------|
| 1. DisplayPort™ 1.2 | 6. Power connector |
| 2. USB 3.1 Gen 2 Type A | 7. WLAN External Antenna Punchout |
| 3. Configurable Option card slot (Choice of DisplayPort™ 1.2, HDMI™ 2.0, VGA, USB Type-C™ with alt mode display, USB Type-C™ with Power Delivery, Discrete Graphics Option Card with DisplayPort™ 1.4, Thunderbolt 3.0, Serial Port, Fiber NIC) | 8. Universal cable lock slot |
| 4. USB 3.1 Gen 1 Type A allows for wake from S4/S5 with keyboard/mouse when connected and enabled in BIOS | 9. Cover Release Thumbscrew |
| 5. RJ-45 Network Adapter | 10. WLAN Internal Antenna |
| | 11. Padlock Loop |

Not Shown

- Slots**
- (1) Internal M.2 2230 connector for WLAN
 - (2) Internal M.2 SSD storage (2230 or 2280 connector)
- Bays**
- (1) 2.5- inch SATA drive Bay
- Mounting Support for**
- VESA 100 mounting system on bottom of PC chassis
 - VESA Sleeve
 - Quick Release Bracket
 - B300/B500 Mounting bracket

Overview

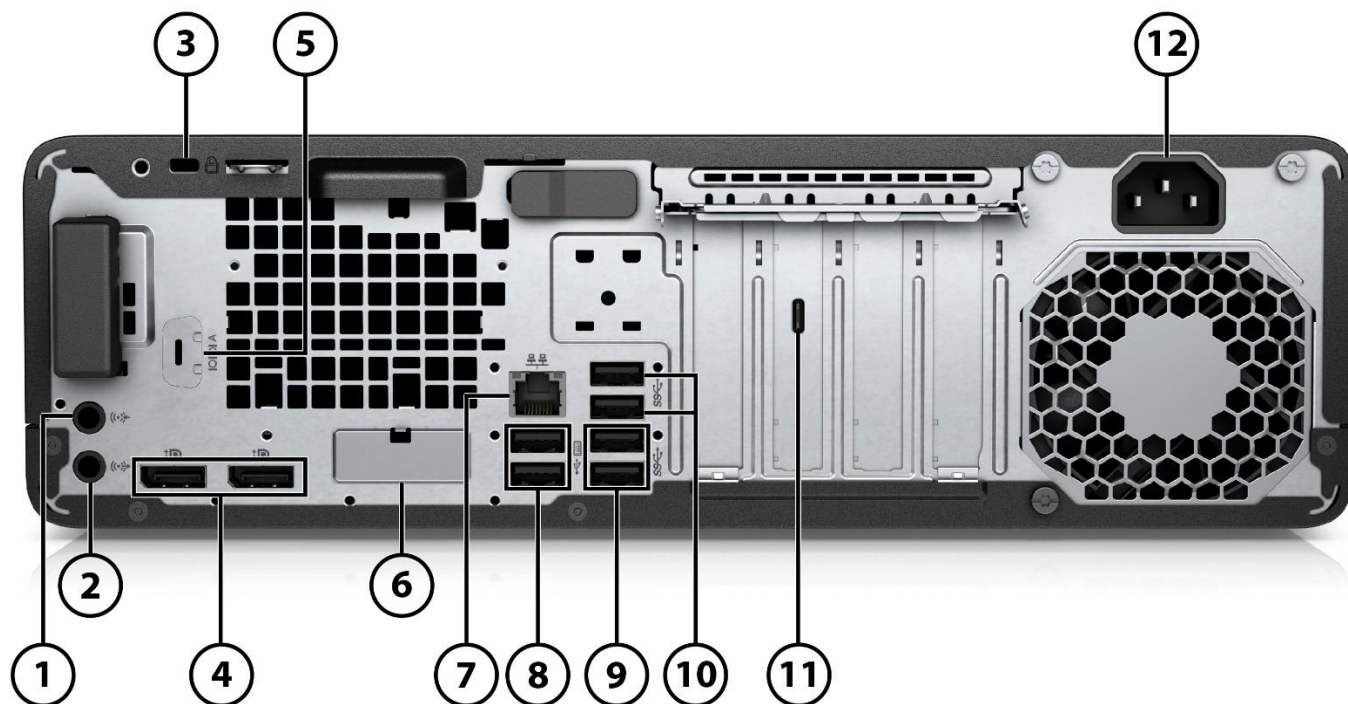
HP EliteDesk 800 G4 Small Form Factor Business PC



- | | |
|--|---|
| 1. Slim optical drive (optional) | 6. USB 2.0 (charge support up to 5V/1.5A) |
| 2. SD 4 Card Reader (optional) | 7. Headphone connector |
| 3. USB Type-C™ port (charge support up to 5V/3A) | 8. Universal Audio Jack with CTIA headset support |
| 4. USB 3.1 Gen2 ports (2) | 9. Hard drive activity light |
| 5. USB 2.0 port | 10. Dual-state power button |

Overview

HP EliteDesk 800 G4 Small Form Factor Business PC (Rear Image)



- | | |
|--|---|
| 1. Audio-in connector | 6. Optional port (DisplayPort™ 1.2, HDMI, VGA or USB-C™) (USB-C™ option has alt mode DisplayPort™ 1.2 or 15W output) - shown here not installed |
| 2. Audio-out connector for powered audio devices | 7. RJ-45 (network) jack |
| 3. Cable lock slot | 8. USB 2.0 ports with wake from S4/S5 (2) |
| 4. Dual-Mode DisplayPort™ 1.2 (2) | 9. USB 3.1 Gen2 ports (2) |
| 5. Optional serial port - shown here not installed | 10. USB 3.1 Gen1 ports (2) |
| | 11. Optional Thunderbolt PCIe card - shown here installed |

Not shown

Slots

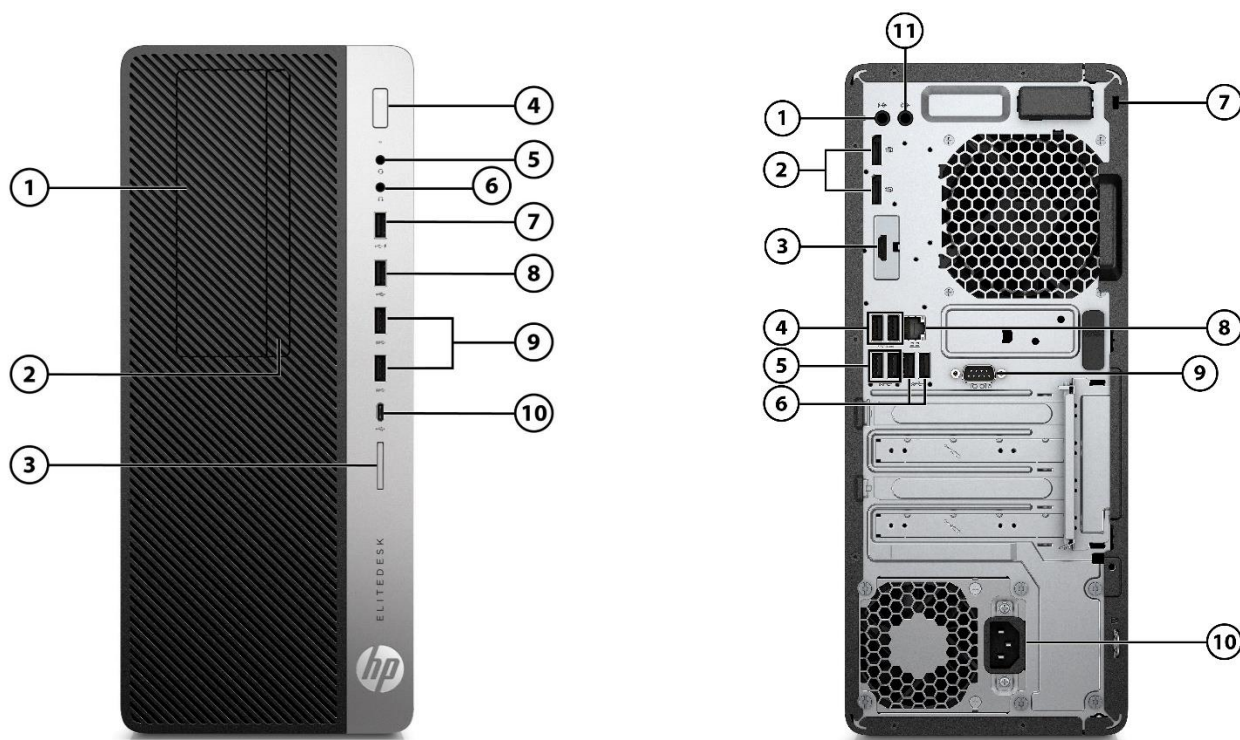
- (2) PCI Express x16 graphics connectors; one wired as an x4
- (2) PCI Express x1
- (2) internal M.2 SSD storage (2230 or 2280 connector)
- (1) internal M.2 WLAN (2230 connector)

Bays

- (1) 2.5" internal storage drive bay
- (2) 3.5" internal storage drive bay (convertible to 2.5")
- (1) 9.5 mm slim optical drive bay

Overview

HP EliteDesk 800 G4 Tower Business PC



1. 5.25-inch Half-Height Drive Bay (behind bezel)
2. Slim optical drive (optional)
3. SD 4 Card Reader (optional)
4. Dual-state power button
5. Universal Audio Jack with CTIA headset support
6. Headphone connector
7. USB 2.0 port (charge support up to 5V/1.5A)
8. USB 2.0 port
9. USB 3.1 Gen2 ports (2)
10. USB Type-C™ port (charge support up to 5V/3A)

1. Audio-out jack for powered audio devices
2. Dual-Mode DisplayPort™ 1.2 (DP++) (2)
3. Optional port (DisplayPort™ 1.2, HDMI, VGA or USB-C™) (USB-C™ option has alt mode DisplayPort™ 1.2 or 15W output) – Shown here HDMI installed
4. USB 2.0 ports with wake from S4/S5 (2)
5. USB 3.1 Gen2 ports (2)
6. USB 3.1 Gen1 ports (2)
7. Cable lock slot
8. RJ-45 (network) jack
9. Optional serial port – shown here installed
10. Power cord connector
11. Audio-in jack

Not shown

Slots

- (2) PCI Express x16 graphics connectors; one wired as an x4
- (2) PCI Express x1
- (2) internal M.2 SSD storage (2230 or 2280 connector)
- (1) internal M.2 WLAN (2230 connector)

Bays

- (1) 2.5" internal storage drive bay
- (2) 3.5" internal storage drive bay (convertible to 2.5")
- (1) 5.25" half-height drive bay
- (1) 9.5mm slim optical drive bay

Overview

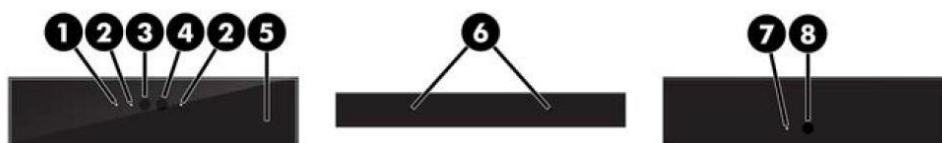
HP EliteOne 800 G4 All-in-One Business PC (23.8" Touch and Non-Touch)



1. Camera (optional)

2. Speakers (optional)

Infrared (IR) and dual facing camera (optional)



1. Camera light

3. Full High Definition (FHD) camera

5. Rear camera adjustment wheel

7. Camera light

2. IR camera light

4. IR camera

6. Digital microphones

8. FHD camera

Full High Definition (FHD) camera (optional)



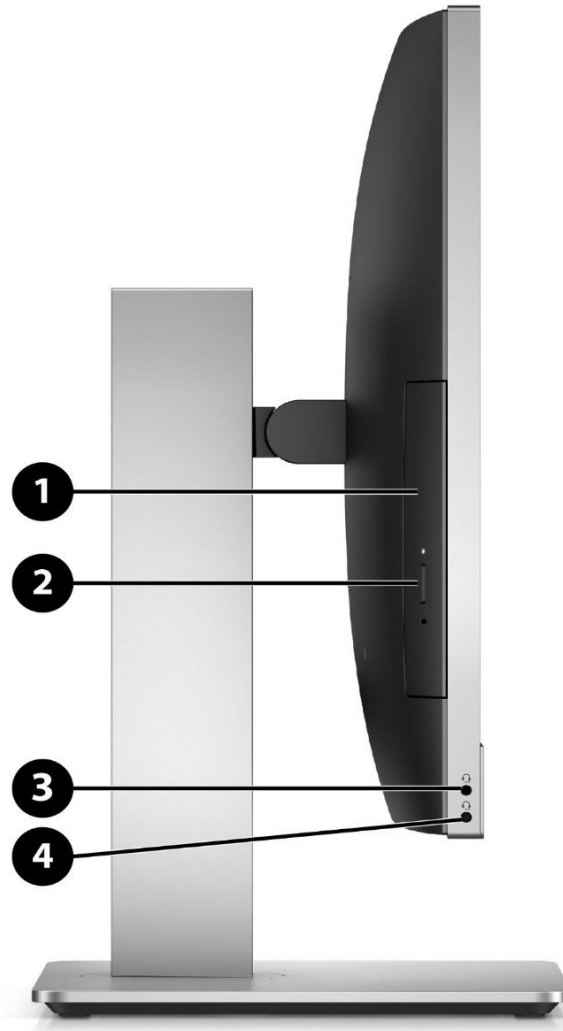
1. Camera light

2. FHD camera

3. Digital microphones

Overview

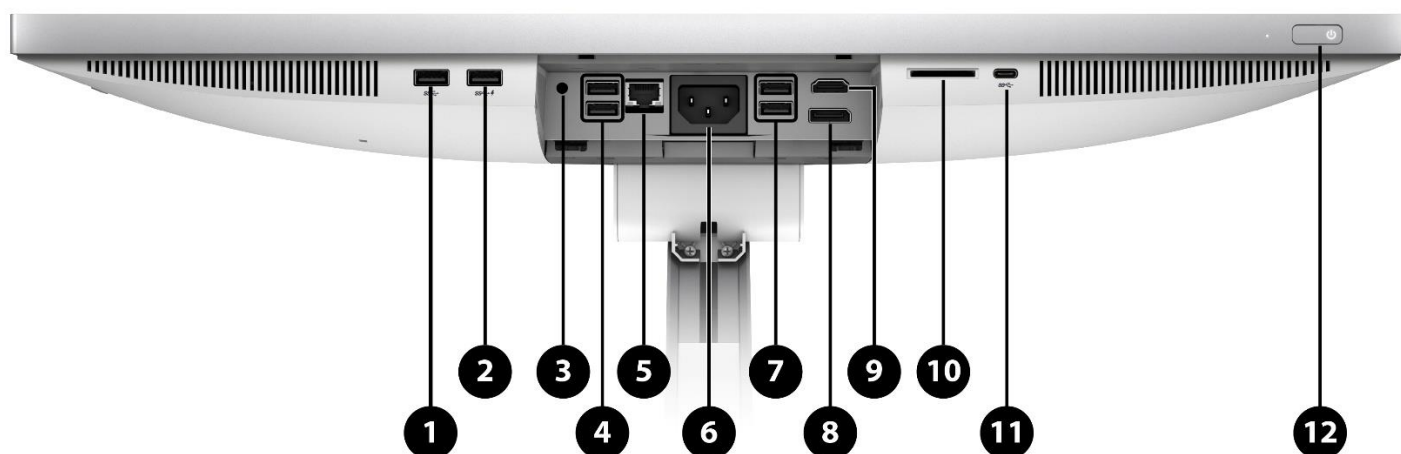
HP EliteOne 800 G4 All-in-One Business PC (23.8" Touch and Non-Touch)



- | | | | |
|----|--|----|--|
| 1. | Optical disc drive (optional) | 3. | Universal Audio Jack with CTIA headset support |
| 2. | Optical disc drive eject button (optional) | 4. | Headphone connector |

Overview

HP EliteOne 800 G4 All-in-One Business PC (23.8" Touch and Non-Touch)



Bottom components and rear ports (behind security cover)

- | | |
|---|---|
| 1. USB 3.1 Gen 2 Type-A | 8. Dual-Mode DisplayPort™ 1.2 (DP++) for integrated graphics models or Dual-Mode DisplayPort™ 1.4 (DP++) for discrete graphics models |
| 2. USB 3.1 Gen 2 Type-A (charge support up to 5V/1.5A) | 9. HDMI connector |
| 3. Audio line-out connector | 10. SD card reader 4.0 (optional) |
| 4. USB 3.1 Gen 2 Type-A ports (2) | 11. USB 3.1 Type-C™ Gen 2 port (charge support up to 5V/3A) |
| 5. RJ-45 (network) jack | 12. Dual-state power button |
| 6. Power connector | |
| 7. USB 3.1 Gen 1 Type-A ports (2) (keyboard/mouse wake capable) | |

Not shown

Slots

- (1) internal M.2 PCIe x1 connector for optional wireless NIC
- (2) internal M.2 PCIe x4 connector for optional m.2 SSD

Bays

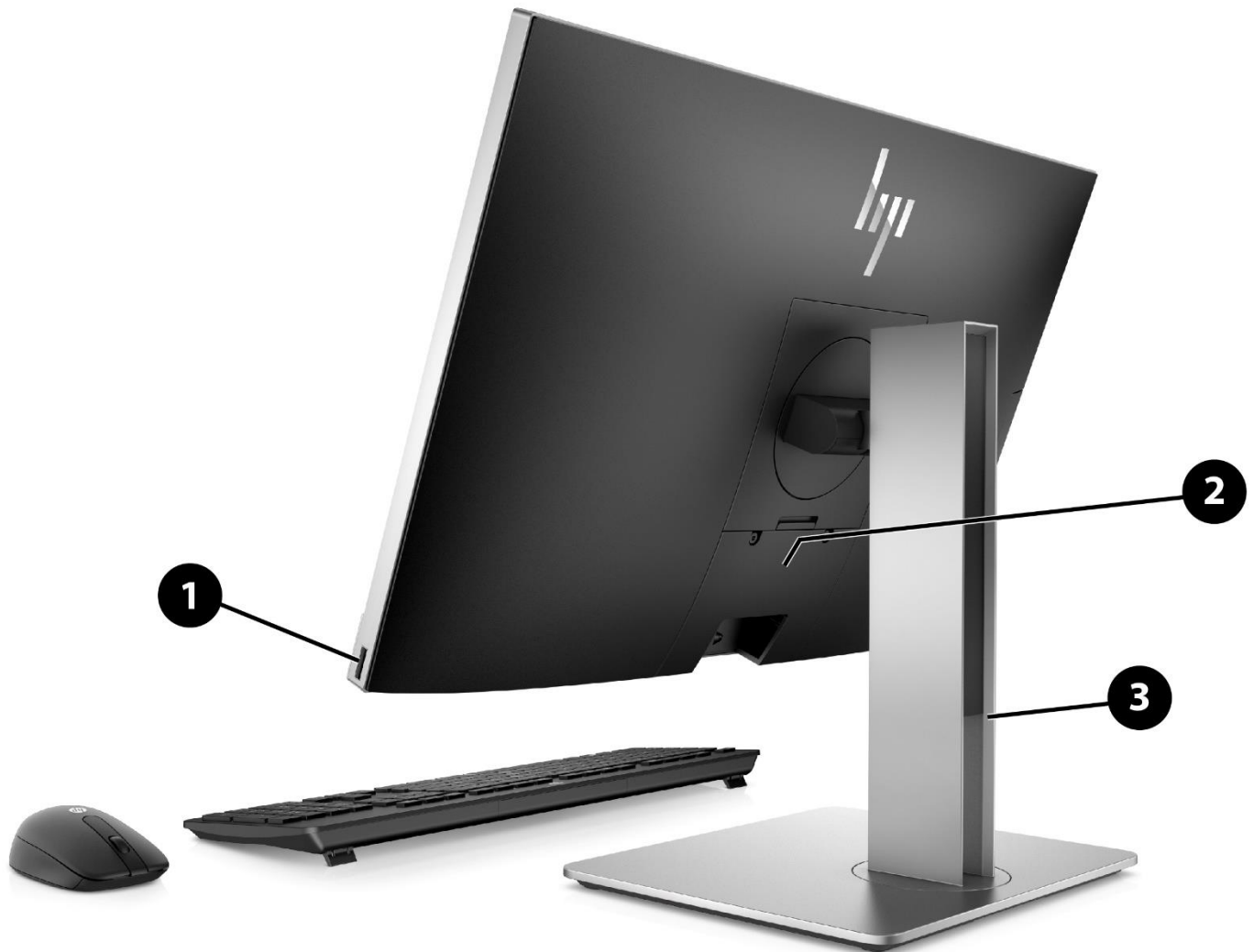
- (1) 2.5" internal storage drive bay

VESA

Support for VESA 100 mounting system on back of PC chassis (mounting hardware sold separately)

Features

HP EliteOne 800 G4 All-in-One Business PC (23.8" Touch and Non-Touch)



Rear and side components

- | | | | |
|----|-------------------------------|----|------------------------------------|
| 1. | Fingerprint reader (optional) | 3. | Adjustable height stand (optional) |
| 2. | Rear port cover | | |

Features

AT A GLANCE

- Choice of four form factors: Tower, Small Form Factor, Desktop Mini and All-In-One (touch/non-touch)
- Intel® Q370 chipset supporting Intel® 8th generation Core™ processors, featuring integrated Intel® UHD Graphics and Intel® vPro™ Technology (available with Core i5 and Core i7 processors) ^{1,4}
- Processors up to 95W on TWR, SFF and DM
- Intel® UHD graphics as well as optional discrete graphics
- Intel® Ethernet Connection I219LM GbE LOM integrated network connection
- DDR4 Synchronous Dynamic Random Access Memory (SDRAM) (Transfer rates up to 2666 MT/s)
- Support for up to three monitors via two standard DisplayPort™ 1.2 connectors and an optional third video port connector which provides the following choices: HDMI, VGA, DisplayPort™ 1.2, or USB Type-C™ with DisplayPort™ 1.2 for all platforms; USB Type-C™ with DisplayPort™ 1.2 and Power Delivery (PD) from Display for 800 G4 DM 35W (see Ports section for port availability by platform). AiO supports up to two additional monitors via DisplayPort™ or HDMI connectors.²
- Configurable 3rd rear I/O with video port (HDMI, DisplayPort™ 1.2, VGA, Type-C™ with DisplayPort™ 1.2) or Thunderbolt 3.0 (port on DM, PCIe card on TWR, SFF)
- Selection of discrete graphic cards to configure systems to up to 7 displays (TWR, SFF and DM 35W)²
- VR ready cards on the 800 G4 TWR
- Models can be configured with multiple data drives in a RAID array
- Skype for Business certified (AiO)
- Audio by Bang & Olufsen (AiO)
- Intel® Unite™ available (AiO)
- EN 60601-1-2: 2015 compliant (AiO)
- Enhanced Security With:
 - HP Sure Click
 - HP Sure Start Gen4
 - HP Sure Run
 - HP Sure Recover
 - HP Manageability Integration Kit
 - HP BIOSphere Gen4
 - HP Client Security Manager Gen4
 - Notification with HP Image Assistant Gen3
- Multifactor Authentication features include fingerprint reader (optional) and IR webcam (optional) both Windows Hello certified (AiO)
- High efficiency energy saving power supply options
- ENERGY STAR® certified. EPEAT® Gold registered where applicable/supported. Registration may vary by country. See <http://www.epeat.net> for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at <http://www.hp.com/go/options>.
- CCC, CECP and SEPA Certified (TWR/SFF/DM)
- CECP Certified (AiO)
- TCO Edge for AiO (AiO)
- PC chassis and all internal components and modules are manufactured with low halogen content ³
- Dust filter available for all platforms (except 65W and 95W Desktop Mini)
- Protected by HP Services, including limited warranties up to 3-3-3 (terms and conditions vary by country; certain restrictions and exclusions apply); Care Packs available with up to 5 years Next Business Day Onsite Hardware Support
- Compliance with CE (Class B) / FCC (Class B) / UL (UL609501) / CSA (CSA C22.2 No.60950-1-07) / ICES-003 / CCC / VCCI (Class B) / KCC (Class B)

1. Multi core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance

2. DisplayPort™ multi-stream monitors 'daisy-chained' together.

3. External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.

Features

4. Some functionality of vPro technology, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vPro technology is dependant on 3rd party software providers. Compatibility of this generation of Intel vPro technology-based hardware with future "virtual appliances" is yet to be determined."

NOTE: See important legal disclosures for all listed specs in their respective features sections

PRODUCT NAME

HP EliteDesk 800 G4 Tower Business PC
 HP EliteDesk 800 G4 Small Form Factor Business PC
 HP EliteDesk 800 G4 Desktop Mini Business PC
 HP EliteOne 800 G4 23.8-inch Touch and Non-Touch All-in-One Business PC

OPERATING SYSTEM

| | |
|---------------------------|---|
| Preinstalled | Windows® 10 Pro 64 ¹ |
| | Windows® 10 Pro 64 (National Academic License) ² |
| | Windows® 10 Home 64 ¹ |
| | Windows® 10 Home Single Language 64 ¹ |
| | FreeDos 2.0 |
| Web-supported only | Windows® 10 Enterprise 64 ¹ |

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com/>.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see <https://aka.ms/ProEducation> for Windows 10 Pro Education feature information.

NOTE: Your product does not support Windows 8 or Windows 7

In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on <http://www.support.hp.com>

CHIPSET

| | DM | SFF | TWR | AiO |
|--------------------------|-----------|------------|------------|------------|
| Intel® Q370 PCH-H- vPro™ | X | X | X | X |

Features

PROCESSORS

| Intel® 8th Generation Core™ Processors | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> |
|--|-----------|------------|------------|------------|
| Intel® Core™ i7 8700K Processor with Intel® UHD Graphics 630 (3.7GHz, up to 4.7 GHz with Intel® Turbo Boost, 12MB cache, 6 cores) 95W ¹ Supports Intel® vPro™Technology ⁴ | X | X | X | |
| Intel® Core™ i7+ 8700K Processor with Intel® UHD Graphics 630 (3.7 GHz, up to 4.7GHz with Intel® Optane™ Memory, 12 MB cache, 6 cores) 95W ^{1,2} Supports Intel® vPro™Technology ⁴ | X | X | X | |
| Intel® Core™ i7 8700 processor with Intel® UHD Graphics 630 (3.2 GHz, up to 4.6 GHz with Intel® Turbo Boost, 12 MB cache, 6 cores) 65W ^{1,3} Supports Intel® vPro™Technology ⁴ | X | X | X | X |
| Intel® Core™ i7+ 8700 processor (Core i7 and 16GB Intel® Optane™ memory) with Intel® UHD Graphics 630 (3.2 GHz, up to 4.6 GHz with Intel® Turbo Boost, 12 MB cache, 6 cores) 65W ^{1,2,3} Supports Intel® vPro™Technology ⁴ | X | X | X | X |
| Intel® Core™ i7 8700T processor with Intel® UHD Graphics 630 (2.4 GHz, up to 4 GHz with Intel® Turbo Boost, 12 MB cache, 6 cores) ^{1,3} Supports Intel® vPro™Technology ⁴ | X | | | |
| Intel® Core™ i7+ 8700T Processor with Intel® UHD Graphics 630 (2.4 GHz, up to 4.0 GHz with Intel® Optane™ Memory, 12 MB cache, 6 cores) ^{1,2} Supports Intel® vPro™Technology ⁴ | X | | | |
| Intel® Core™ i5 8600K Processor with Intel® UHD Graphics 630 (up to 3.6GHz, 9MB cache, 6 cores) 95W ¹ Supports Intel® vPro™Technology ⁴ | X | X | X | |
| Intel® Core™ i5+ 8600K processor (Core i5 and 16GB Intel® Optane™ memory) with Intel® HD Graphics 630 (3.1 GHz, up to 4.3 GHz with Intel® Turbo Boost, 9 MB cache, 6 cores) ^{1,2,3} Supports Intel® vPro™Technology ⁴ | X | X | X | |
| Intel® Core™ i5 8600 processor with Intel® UHD Graphics 630 (3.1 GHz, up to 4.3 GHz with Intel® Turbo Boost, 9 MB cache, 6 cores) ^{1,3} Supports Intel® vPro™Technology ⁴ | X | X | X | X |
| Intel® Core™ i5+ 8600 processor (Core i5 and 16GB Intel® Optane™ memory) with Intel® UHD Graphics 630 (3.1 GHz, up to 4.3 GHz with Intel® Turbo Boost, 9 MB cache, 6 cores) ^{1,2,3} Supports Intel® vPro™Technology ⁴ | X | X | X | X |
| Intel® Core™ i5 8500 processor with Intel® UHD Graphics 630 (3.0 GHz, up to 4.1 GHz with Intel® Turbo Boost, 9 MB cache, 6 cores) ^{1,3} Supports Intel® vPro™Technology ⁴ | X | X | X | X |
| Intel® Core™ i5+ 8500 processor (Core i5 and 16GB Intel® Optane™ memory) with Intel® UHD Graphics 630 (3.0 GHz, up to 4.1 GHz with Intel® Turbo Boost, 9 MB cache, 6 cores) ^{1,2,3} Supports Intel® vPro™Technology ⁴ | X | X | X | X |
| Intel® Core™ i5 8500T processor with Intel® UHD Graphics 630 (2.1 GHz, up to 3.5 GHz with Intel® Turbo Boost, 9 MB cache, 6 cores) ^{1,3} Supports Intel® vPro™Technology ⁴ | X | | | |
| Intel® Core™ i5+ 8500T Processor with Intel® UHD Graphics 630 (2.1 GHz, up to 3.5 GHz with 16GB Intel® Optane™ Memory, 9 MB cache, 6 cores) ^{1,2} Supports Intel® vPro™Technology ⁴ | X | | | |

Features

| | | | | |
|--|----------|----------|----------|----------|
| Intel® Core™ i5 8600T processor with Intel® UHD Graphics 630 (2.3 GHz, up to 3.7 GHz with Intel® Turbo Boost, 9 MB cache, 6 cores) ^{1,3} Supports Intel® vPro™Technology ⁴ | X | | | |
| Intel® Core™ i5+ 8600T Processor with Intel® UHD Graphics 630 (2.3 GHz, up to 3.7 GHz with 16GB Intel® Optane™ Memory, 9 MB cache, 6 cores) ^{1,2} Supports Intel® vPro™Technology ⁴ | X | | | |
| Intel® Core™ i3 8300 processor with Intel® UHD Graphics 630 (3.7 GHz, 8 MB cache, 4 cores) ¹ | X | X | X | X |
| Intel® Core™ i3 8100 processor with Intel® UHD Graphics 630 (3.6 GHz, 6 MB cache, 4 cores) ¹ | X | X | X | X |
| Intel® Core™ i3 8100T processor with Intel® UHD Graphics 630 (3.1 GHz, 6 MB cache, 4 cores) ¹ | X | | | |
| Intel® Core™ i3 8300T processor with Intel® UHD Graphics 630 (3.2 GHz, 8 MB cache, 4 cores) ¹ | X | | | |

| Intel® 8th Generation Pentium® Processors | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> |
|--|------------------|-------------------|-------------------|-------------------|
| Intel® Pentium® Gold G5600 processor with Intel® UHD Graphics 630 (3.9 GHz, 4 MB cache, 2 cores) ¹ | X | X | X | X |
| Intel® Pentium® Gold G5500 processor with Intel® UHD Graphics 630 (3.8 GHz, 4 MB cache, 2 cores) ¹ | X | X | X | X |
| Intel® Pentium® Gold G5400 processor with Intel® UHD Graphics 610 (3.7 GHz, 4 MB cache, 2 cores) ¹ | X | X | X | X |
| Intel® Pentium® Gold G5400T processor with Intel® UHD Graphics 610 (3.1 GHz, 4 MB cache, 2 cores) ¹ | X | | | |
| Intel® Pentium® Gold G5500T processor with Intel® UHD Graphics 630 (3.2 GHz, 4 MB cache, 2 cores) ¹ | X | | | |

| Intel® 8th Generation Celeron™ Processors | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> |
|---|------------------|-------------------|-------------------|-------------------|
| Intel® Celeron® G4900 processor with Intel® UHD Graphics 610 (3.1 GHz, 2 MB cache, 2 cores) ¹ | X | X | X | X |
| Intel® Celeron® G4900T processor with Intel® UHD Graphics 610 (2.9 GHz, 2 MB cache, 2 cores) ¹ | X | | | |
| Intel® Celeron® G4920 processor with Intel® UHD Graphics 610 (3.2 GHz, 2 MB cache, 2 cores) ¹ | X | | | |

1: Multi-core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

2. Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system.

3. Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See <http://www.intel.com/technology/turboboost> for more information.

4. Some functionality of vPro technology, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vPro technology is dependant on 3rd party software providers. Compatibility of this generation of Intel vPro technology-based hardware with future "virtual appliances" is yet to be determined."

Features

GRAPHICS

Integrated Intel® Graphics

| | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> |
|---|-----------|------------|------------|------------|
| Intel® UHD Graphics 630 (integrated on 8th gen Core i7/i5/i3, Pentium® Gold G5600, G5500) | X | X | X | X |
| Intel® UHD Graphics 610 (integrated on 8th gen Pentium® Gold G5400, Celeron® G4900) | X | X | X | X |

Optional Discrete Graphics Solutions

| | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> |
|--|-----------|------------|------------|------------|
| AMD® Radeon™ RX550 4GB 2DP 1HDMI Graphics Card | | | X | |
| AMD® Radeon™ RX560 4GB GDDR5 | X | | | X |
| AMD® Radeon™ RX580 4GB FH PCIe x16* | | | X | |
| AMD® Radeon™ RX580 8GB FH GDDR5* | | | X | |
| AMD® Radeon™ R7 430 2GB VGA+DP Graphics Card | | | X | |
| AMD® Radeon™ R7 430 2GB GDDR5 64bit DP+VGA | | X | | |
| AMD® Radeon™ R7 430 2GB GDDR5 64bit 2DP | | X | X | |
| AMD® Radeon™ R7 430 2GB 2DP Graphics Card | | X | X | |
| NVIDIA® GeForce® GT730 2GB DP DVI PCIe x8 GFX | | X | X | |
| NVIDIA® GeForce® GTX 1060 3GB Graphics Card* | | | X | |
| NVIDIA® GeForce® RTX 2080 8GB GDDR6* | | | X | |
| NVIDIA® Quadro P620 2GB Graphics Card | | | X | |
| NVIDIA® Quadro P400 2GB Graphics Card | | X | X | |

*Requires 500W chassis

Adapters and Cables

| | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> |
|------------------------------------|-----------|------------|------------|------------|
| HP DisplayPort™ Cable | X | X | X | X |
| HP DisplayPort™ to DVI-D Adapter | X | X | X | X |
| HP DisplayPort™ to HDMI 4K Adapter | X | X | X | X |
| HP DisplayPort™ to VGA Adapter | X | X | X | X |
| HP USB-C™ to USB 3.0 | X | X | X | X |
| HP USB to Serial Port Adapter | X | X | X | X |

STORAGE

3.5 inch SATA Hard Disk Drives (HDD)

| | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> |
|------------------------------|-----------|------------|------------|------------|
| 500GB 7200RPM 3.5in SATA HDD | | X | X | |
| 1TB 7200RPM 3.5in SATA HDD | | X | X | |
| 2TB 7200RPM 3.5in SATA HDD | | X | X | |

2.5 inch SATA Hard Disk Drives (HDD)

| | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> |
|------------------------------|-----------|------------|------------|------------|
| 500GB 7200RPM 2.5in SATA HDD | X | X | X | X |
| 1TB 7200RPM 2.5in SATA HDD | X | X | X | X |
| 2TB 5400RPM 2.5in SATA HDD | X | X | X | X |

Features

| | | | | |
|---|----------|----------|----------|----------|
| 500GB 7200RPM 2.5in Self Encrypted OPAL2 SATA HDD | X | X | X | X |
| 500GB 7200RPM 2.5in Self Encrypted Federal Information Processing Standard SATA HDD | X | X | X | X |

2.5 inch SATA Solid State Hybrid Drives (SSHD)

| | DM | SFF | TWR | AiO |
|-------------------------------|-----------|------------|------------|------------|
| 500GB 5400RPM 2.5in SATA SSHD | X | X | X | X |
| 1TB 5400RPM 2.5in SATA SSHD | X | X | X | X |
| 2TB 5400RPM 2.5in SATA SSHD | X | X | X | X |

2.5 inch Solid State Drives (SSD)

| | DM | SFF | TWR | AiO |
|---|-----------|------------|------------|------------|
| 128GB 2.5in SATA Three Layer Cell SSD | X | X | X | X |
| 256GB 2.5in SATA Three Layer Cell SSD | X | X | X | X |
| 512GB 2.5in SATA Three Layer Cell SSD | X | X | X | X |
| 256GB 2.5in SATA Self Encrypted OPAL2 Three Layer Cell SSD | X | X | X | X |
| 512GB 2.5in SATA Self Encrypted OPAL2 Three Layer Cell SSD | X | X | X | X |
| 256GB 2.5in SATA Self Encrypted Federal Information Processing Standard SSD | X | X | X | X |
| 512GB 2.5in SATA Self Encrypted Federal Information Processing Standard SSD | X | X | X | X |

M.2 PCIe NVMe Solid State Drives (SSD)

| | DM | SFF | TWR | AiO |
|--|-----------|------------|------------|------------|
| 128GB M.2 2280 PCIe NVMe SSD | X | X | X | X |
| 256GB M.2 2280 PCIe NVMe SSD | X | X | X | X |
| 512GB M.2 2280 PCIe NVMe SSD | X | X | X | X |
| 128GB M.2 2280 PCIe NVMe Three Layer Cell SSD | X | X | X | X |
| 256GB M.2 2280 PCIe NVMe Three Layer Cell SSD | X | X | X | X |
| 512GB M.2 2280 PCIe NVMe Three Layer Cell SSD | X | X | X | X |
| 1TB M.2 2280 PCIe NVMe Three Layer Cell SSD | X | X | X | X |
| 256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD | X | X | X | X |
| 512GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD | X | X | X | X |
| | | | | |

Optical Disc Drives

| | DM | SFF | TWR | AiO |
|------------------------------------|-----------|------------|------------|------------|
| HP 9.5mm Slim DVD-ROM Drive | | X | X | X |
| HP 9.5mm Slim DVD Writer Drive | | X | X | X |
| HP 9.5mm Slim Blu-Ray Writer Drive | | X | X | X |

Media Card Reader

| | DM | SFF | TWR | AiO |
|---|-----------|------------|------------|------------|
| SD 4.0 with 5-in-1 Interface (Supports SD, SDXC, SDHC, UHS-I, UHS-II) | | X | X | X |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Features

MEMORY

Memory Type

| | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> |
|---|-----------|------------|------------|------------|
| DDR4-2666 (Transfer rates up to 2666 MT/s), 32 GB, 2 SODIMM | X | | | X |
| DDR4-2666 (Transfer rates up to 2666 MT/s), 64 GB, 4 DIMM | | X | X | |

Memory Configuration

| | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> |
|-------------------|-----------|------------|------------|------------|
| 4 GB (1 x 4 GB) | X | X | X | X |
| 8 GB (2 x 4 GB) | X | X | X | X |
| 8 GB (1 x 8 GB) | X | X | X | X |
| 16 GB (2 x 8 GB) | X | X | X | X |
| 16 GB (1 x 16 GB) | X | X | X | X |
| 32 GB (2 x 16 GB) | X | X | X | X |
| 32 GB (4 x 8 GB) | | X | X | |
| 64 GB (4 x 16 GB) | | X | X | |

NOTE: For systems configured with more than 3 GB of memory and a 32-bit operating system, all memory may not be available due to system resource requirements. Addressing memory above 4 GB requires a 64-bit operating system.

Memory modules support data transfer rates up to 2666 MT/s; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate.

NOTE: All memory slots are customer accessible / upgradeable.

NETWORKING/COMMUNICATIONS

Ethernet (RJ-45) Integrated

| | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> |
|--|-----------|------------|------------|------------|
| Intel® I219-LM Gigabit Network Connection LOM (standard) | X | X | X | X |
| Intel® Ethernet I210-T1 PCIe x1 Gb Network Interface Card (optional) | | X | X | |

Wireless¹

| | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> |
|--|-----------|------------|------------|------------|
| Intel® 9560 802.11AC 2x2 with Bluetooth® M.2 Combo Card vPro™ | X | X | X | X |
| Intel® 9560 802.11AC 2x2 with Bluetooth® M.2 Combo Card non-vPro™ | X | X | X | X |
| Realtek RTL8822BE 802.11ac 2x2 with Bluetooth® M.2 Combo Card | | X | X | X |
| Realtek RTL8821CE 802.11ac 1x1 with Bluetooth® M.2 Combo Card | | X | X | X |
| Intel® 7265 802.11AC 2x2 with Bluetooth® M.2 Combo Card non-vPro™ (Brazil) | X | X | | |
| Intel® 7265 802.11AC 2x2 M.2 Combo Card non-vPro™ with external antenna (Brazil) | X | X | | |

1. Wireless access point and Internet service required and not included. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices

Features

KEYBOARDS AND POINTING DEVICES

Keyboards

| | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> |
|--|-----------|------------|------------|------------|
| HP USB Conferencing Keyboard | X | X | X | X |
| HP Wireless Collaboration Keyboard | X | X | X | X |
| HP USB and PS/2 Washable Keyboard ¹ | X | X | X | X |
| HP USB Smart Card (CCID) Keyboard | X | X | X | X |
| HP USB Business Slim Keyboard | X | X | X | X |
| HP USB Keyboard | X | X | X | X |
| HP PS/2 Business Slim Keyboard ¹ | | X | X | |
| HP PS/2 Keyboard ¹ | | X | X | |
| HP Wireless Business Slim Keyboard and Mouse | X | X | X | X |

Mouse

| | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> |
|---|-----------|------------|------------|------------|
| HP PS/2 Mouse ¹ | | X | X | |
| HP USB Optical Mouse | X | X | X | X |
| HP USB Premium Mouse | X | X | X | X |
| HP USB 1000dpi Laser Mouse | X | X | X | X |
| HP USB and PS/2 Washable Mouse ¹ | | X | X | X |
| Antimicrobial USB Mouse ² | X | X | X | X |
| HP USB Hardened Mouse ² | X | X | X | X |

1. PS/2 port not available on EliteOne 800 G4 AiOs

2. Not available in all regions

Features

SECURITY

| | DM | SFF | TWR | AiO |
|---|-----------|------------|------------|------------|
| Trusted Platform Module (TPM) 2.0 (Infineon SLB9670). Common Criteria EAL4+ Certified. FIPS 140-2 Level 2 Certified | X | X | X | X |
| Solenoid Lock & Intrusion Sensor | | X | X | |
| Intrusion Sensor for DM/AiO (integrated in the PCA, can be enabled/disabled through BIOS) | X | | | X |
| Support for chassis cable lock devices | X | X | X | X |
| Support for chassis padlocks devices | X | X | X | |
| HP Fingerprint Reader (standard on 800 G4 AiO touch models and optional on non-touch models) | | | | X |
| SATA port disablement (via BIOS) | X | X | X | X |
| Serial, USB enable/disable (via BIOS) | X | X | X | X |
| Intel® Identify Protection Technology (IPT) ¹ | X | X | X | X |
| Serial, parallel, USB enable/disable (via BIOS) | X | X | X | X |
| Optional USB Port Disable at factory (user configurable via BIOS) | X | X | X | X |
| Removable media write/boot control | X | X | X | X |
| Power-on password (via BIOS) | X | X | X | X |
| Setup password (via BIOS) | X | X | X | X |

1. Models configured with Intel® Core™ processors have the ability to utilize advanced security protection for online transactions. IPT, used in conjunction with participating web sites, provides double identity authentication by adding a hardware component in addition to the usual user name and password. IPT is initialized through an HP Client Security module.

Features

PORTS

I/O Ports – Standard

| | DM | SFF | TWR | AiO |
|------------------------------|--|---|--|--|
| USB 2.0 | N/A | 2 including 1 fast charging (front); 2 including wake from S4/S5 (rear) | 2 including 1 fast charging (front); 2 including wake from S4/S5 (rear) | N/A |
| USB 3.1 Gen 1 | 1 front, 2 rear | 2 rear | 2 rear | 2 rear |
| USB 3.1 Gen 2 | 1 front, 2 rear | 2 front; 2 rear | 2 front; 2 rear | 4 rear |
| USB Type-C™ 3.1 Gen 2 (15 W) | 1 front; 1 rear (option) | 1 front; 1 rear (option) | 1 front; 1 rear (option) | 1 rear |
| Video | 2 DisplayPort™ 1.2 (rear) 1 Configurable video port (rear) (Choice of DisplayPort™ 1.2, HDMI™ 2.0, VGA, or USB Type-C™ with alt mode display port and power delivery) For models with discrete graphics: 1 DisplayPort™ 1.4 (rear) | 2 DisplayPort™ 1.2 (rear) 1 Configurable video port (rear) (Choice of DisplayPort™ 1.2, HDMI™ 2.0, VGA, or USB Type-C™ with alt mode display or 15W output) | 2 DisplayPort™ 1.2 (rear) 1 Configurable video port (rear) (Choice of DisplayPort™ 1.2, HDMI™ 2.0, VGA, or USB Type-C™ with alt mode display port or 15W output) | For models with integrated graphics: 1 DisplayPort™ 1.2 (rear) 1 HDMI™ 2.0 (rear) For models with discrete graphics: 1 DisplayPort™ 1.4 (rear) 1 HDMI™ 2.0 (rear) |
| Audio | 1 Headphone (front), 1 Universal Audio Jack with CTIA headset support (front)) | 1 Headphone (front), 1 Universal Audio Jack with CTIA headset support (front)); 1 Audio-out (rear), 1 Audio-in (rear) | 1 Headphone (front), 1 Universal Audio Jack with CTIA headset support (front)); 1 Audio-out (rear), 1 Audio-in (rear) | 1 Line out (rear) 1 CTIA UAJ (side) 1 Audio out (side) |
| Network Interface | RJ45 | RJ45 | RJ45 | RJ45 |

I/O Ports – Optional

| | DM | SFF | MT | |
|--------------------------------------|------------------|-------------------|-------------------|-----|
| Serial (RS-232) | 1 (rear)(option) | 1 (rear) (option) | 1 (rear) (option) | N/A |
| Serial (RS-232) and PS/2 combination | N/A | 1 (rear) (option) | 1 (rear) (option) | N/A |

Features

I/O Ports – Internal Ports

| | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> |
|--|------------------|-------------------|-------------------|-------------------|
| Internal SATA storage connector(s) | N/A | 3 | 4 | 2 |
| Internal SATA storage connector (Data and Power) | 1 | N/A | N/A | N/A |

NOTE: For Desktop Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after market option).

Slots

| | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> |
|------------------------------------|--|--|--|--|
| M.2 PCIe | (1) M.2 PCIe x1 2230 (for WLAN) (2) M.2 PCIe x4 2280/2230 Combo (for storage) | (1) M.2 PCIe x1 2230 (for WLAN) (2) M.2 PCIe x4 2280/2230 Combo (for storage) | (1) M.2 PCIe x1 2230 (for WLAN) (2) M.2 PCIe x4 2280/2230 Combo (for storage) | (1) M.2 PCIe x1 2230 (for WLAN) (2) M.2 PCIe x4 2280/2230 Combo (for storage) |
| PCI Express v3.0 x1 | N/A | 2 | 2 | N/A |
| PCI Express v3.0 x16 (wired as x4) | N/A | 1 | 1 | N/A |
| PCI Express v3.0 x16 | N/A | 1 | 1 | N/A |

Bays

| | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> |
|-----------------------------------|------------------|-------------------|-------------------|-------------------|
| 5.25" Half Height | N/A | N/A | 1 | N/A |
| 9mm Slim Optical Disc Drive (ODD) | N/A | 1 | 1 | 1 |
| SD Card Reader | N/A | 1 | 1 | 1 |
| 2.5" Internal Storage Drive | 1 | 1 | 1 | 1 |
| 3.5" Internal Storage Drive | N/A | 2 | 2 | N/A |

NOTE: The TWR can support a single graphics card up to 75W. When configured with dual graphics cards support is limited to 35W for each.

Features

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

BIOS

- HP BIOSphere Gen4 ¹⁷
- HP DriveLock & Automatic DriveLock
- BIOS Update via Network
- Master Boot Record Security
- Power On Authentication
- HP Secure Erase ¹⁸
- Absolute Persistence Module ¹⁹
- Pre-boot Authentication
- HP Wireless Wakeup

Software

- HP Native Miracast Support ¹⁵
- HP Hotkey Support - CMIT
- HP Recovery Manager
- HP JumpStart
- HP Support Assistant ²¹
- HP Noise Cancellation Software
- Buy Office (sold separately)
- Intel® Unite (optional for AiOs)

Manageability Features

- HP Driver Packs ²²
- HP System Software Manager (SSM)
- HP BIOS Config Utility (BCU)
- HP Client Catalog
- HP Manageability Integration Kit Gen2 ²³
- Ivanti Management Suite ²⁴

Client Security Software

- HP Client Security Suite Gen4 ²⁵ including:
 - HP Security Manager ²⁶ (including Credential Manager, HP Password Manager, HP Spare Key)
 - HP Fingerprint Sensor ³¹
 - HP Device Access Manager
 - HP Power On Authentication
 - Windows Defender ²⁷

Features

Security Management

HP Secure Erase¹⁸

TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)³²

SATA 0,1 port disablement (viaBIOS)

RAID configurations³³

Serial, USB enable/disable (viaBIOS)

Power-on password (viaBIOS)

Setup password (viaBIOS)

Support for chassis padlocks and cable lock devices

Integrated hood sensor

HP Sure Click³⁸

HP Sure Start Gen4³⁰

HP Sure Run³⁵

HP Sure Recover³⁶

15. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming

17. HP BIOSphere Gen4 requires Intel® or AMD® 8th Gen processors. Features may vary depending on the platform and configurations.

18. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method.

19. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit:

<http://www.absolute.com/company/legal/agreements/computrace-agreement>. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

21. HP Support Assistant requires Windows and Internet access.

22. HP Driver Packs not preinstalled, however available for download at <http://www.hp.com/go/clientmanagement>.

23. HP Manageability Integration Kit can be downloaded from <http://www.hp.com/go/clientmanagement>.

24. Ivanti Management Suite subscription required.

25. HP Client Security Suite Gen4 requires Windows and Intel® or AMD® 8th generation processors.

26. HP Password Manager requires Internet Explorer or Chrome or FireFox. Some websites and applications may not be supported. User may need to enable or allow the add-on / extension in the internet browser.

27. Windows Defender Opt in Windows 10 and internet connection required for updates.

30. HP Sure Start Gen4 is available on HP EliteBook products equipped with Intel® 8th generation processors

31. HP Fingerprint Sensor available on 800 G4 AiO touch models and optional on 800 G4 AiO non-touch models

32. Firmware TPM is version 2.0. Hardware TPM is v1.2, which is a subset of the TPM 2.0 specification version v0.89 as implemented by Intel Platform Trust Technology (PTT).

33. RAID configuration is optional and does require a second hard drive. . RAID 1 is pre-installed and functionality will require a second hard drive.

35. HP Sure Run is available on HP Elite products equipped with 8th generation Intel® or AMD® processors.

36. HP Sure Recover is available on HP Elite PCs with 8th generation Intel® or AMD® processors and requires an open, wired network connection. Not available on platforms with multiple internal storage drives, Intel® Optane™. You must back up important files, data, photos, videos, etc. before use to avoid loss of data.

38. HP Sure Click is available on select HP platforms and supports Microsoft® Internet Explorer, Google Chrome, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode. Check

<http://h20195.www2.hp.com/v2/GetDocument.aspx?docname=4AA7-0922ENW> for all compatible platforms as they become available.

Features

ENVIRONMENTAL & INDUSTRY

ENERGY STAR® certified models available

EPEAT® registered where applicable/supported. See <http://www.epeat.net> for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at <http://www.hp.com/go/options>.
Low halogen (chassis, all internal components and modules)¹
TAA compliant models available

1. External power supplies, power cords, cables and peripherals are not Low Halogen. Service parts obtained after purchase may not be Low Halogen.

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

| | |
|----------------------------------|---|
| Temperature Range | Operating: 50° to 95° F (10° to 35° C) ¹ Non-operating: -22° to 140° F (-30° to 60° C) |
| Relative Humidity | Operating: 10% to 90% (non-condensing at ambient) Non-operating: 5% to 95% (non-condensing at ambient) |
| Maximum Altitude (unpressurized) | Operating: 5000m Non-operating: 50000ft (15240 m) |

1. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

Features

HP EliteDesk 800 Desktop Mini G4 series

| | | | |
|---|---|--|--------------|
| Eco-Label Certifications & declarations | This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: <ul style="list-style-type: none">• IT ECO declaration• US ENERGY STAR®• EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options. | | |
| System Configuration | The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a "Typically Configured Desktop." | | |
| Energy Consumption (in accordance with US ENERGY STAR® test method) | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 50Hz |
| Normal Operation (Short idle) | 13.599 | 13.514 | 13.099 |
| Normal Operation (Long idle) | 12.211 | 11.765 | 12.367 |
| Sleep | 1.318 | 1.312 | 1.322 |
| Off | 0.616 | 0.618 | 0.618 |
| | NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system. | | |
| Heat Dissipation* | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 50Hz |
| Normal Operation (Short idle) | 46.3726 | 46.0827 | 44.6676 |
| Normal Operation (Long idle) | 41.6395 | 40.1187 | 42.1715 |
| Sleep | 4.4944 | 4.4739 | 4.508 |
| Off | 2.1006 | 2.1074 | 2.1074 |
| | NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour. | | |
| Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) | Sound Power (L _{WAd} , bels) | Sound Pressure (L _{pAm} , decibels) | |
| Typically Configured – Idle | 3.1 | 20 | |
| Fixed Disk – Random writes | 4.4 | 33 | |
| Longevity and Upgrading | This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "5" years after the end of production. | | |
| Batteries | This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight Batterv size: CR2032 (coin cell) | | |

Features

| | | | |
|-------------------------------|--|-------------------------------------|--|
| | Battery type: Lithium | | |
| Additional Information | <ul style="list-style-type: none"> • This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • This product is in compliance with the IEEE 1680 (EPEAT) standard at the <gold> level in the U.S. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains 0% post-consumer recycled plastic (by wt.) • This product is 95.1% recycle-able when properly disposed of at end of life. | | |
| Packaging Materials | External: | PAPER/Corrugated | |
| | Internal: | PLASTIC/EPE (Expanded Polyethylene) | |
| | | PLASTIC/Polyethylene low density | |
| Material Usage | <p>This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):</p> <ul style="list-style-type: none"> • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) | | |

Features

| | |
|---|---|
| Packaging Usage | <p>This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):</p> <ul style="list-style-type: none"> • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) |
| End-of-life Management and Recycling | <p>HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.</p> <p>The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.</p> <p>Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html</p> <p>Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html</p> <p>ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf</p> |

Features

HP EliteDesk 800 Small Form Factor G4 series

| | | | |
|---|---|--|--------------|
| Eco-Label Certifications & declarations | This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: <ul style="list-style-type: none">• IT ECO declaration• US ENERGY STAR®• EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options. | | |
| System Configuration | The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a "Typically Configured Desktop." | | |
| Energy Consumption (in accordance with US ENERGY STAR® test method) | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 50Hz |
| Normal Operation (Short idle) | 12.055 | 12.08 | 12.501 |
| Normal Operation (Long idle) | 11.68 | 11.908 | 11.766 |
| Sleep | 1.101 | 1.1644 | 1.1769 |
| Off | 0.6302 | 0.6258 | 0.9127 |
| | NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system. | | |
| Heat Dissipation* | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 50Hz |
| Normal Operation (Short idle) | 41.1076 | 41.1928 | 42.6284 |
| Normal Operation (Long idle) | 39.8288 | 40.6063 | 40.1221 |
| Sleep | 3.7544 | 3.9706 | 4.0132 |
| Off | 2.149 | 2.134 | 2.1585 |
| | NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour. | | |
| Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) | Sound Power (L _{WAd} , bels) | Sound Pressure (L _{pAm} , decibels) | |
| Typically Configured – Idle | 3.3 | 25 | |
| Fixed Disk – Random writes | 3.3 | 25 | |
| Longevity and Upgrading | This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "5" years after the end of production. | | |
| Batteries | This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight Batterv size: CR2032 (coin cell) | | |

Features

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|-------------------------------|--|-------------------------------------|--|
| | Battery type: Lithium | | |
| Additional Information | <ul style="list-style-type: none"> • This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • This product is in compliance with the IEEE 1680 (EPEAT) standard at the <gold> level in the U.S. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains 0% post-consumer recycled plastic (by wt.) • This product is 95.1% recycle-able when properly disposed of at end of life. | | |
| Packaging Materials | External: | PAPER/Corrugated | |
| | Internal: | PLASTIC/EPE (Expanded Polyethylene) | |
| | | PLASTIC/Polyethylene low density | |
| Material Usage | <p>This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):</p> <ul style="list-style-type: none"> • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBEBs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) | | |
| Packaging Usage | <p>HP follows these guidelines to decrease the environmental impact of product packaging:</p> <ul style="list-style-type: none"> • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. | | |

Features

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| End-of-life Management and Recycling | <p>HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.</p> <p>The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.</p> <p>Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html</p> <p>Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html</p> <p>ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf</p> |
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Features

HP EliteDesk 800 Tower G4 series

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| Eco-Label Certifications & declarations | This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: <ul style="list-style-type: none">• IT ECO declaration• US ENERGY STAR®• EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options. | | |
| System Configuration | The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a Typically Configured Desktop. | | |
| Energy Consumption (in accordance with US ENERGY STAR® test method) | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 60Hz |
| Normal Operation (Short idle) | 17.22 W | 15.78 W | 17.40 W |
| Normal Operation (Long idle) | 16.51 W | 15.22 W | 16.42 W |
| Sleep | 1.38 W | 1.36 W | 1.39 W |
| Off | 0.77 W | 0.79 W | 0.78 W |
| | NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system. | | |
| Heat Dissipation* | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 60Hz |
| Normal Operation (Short idle) | 60 BTU/hr | 54 BTU/hr | 59 BTU/hr |
| Normal Operation (Long idle) | 56 BTU/hr | 52 BTU/hr | 56 BTU/hr |
| Sleep | 5 BTU/hr | 5 BTU/hr | 5 BTU/hr |
| Off | 3 BTU/hr | 3 BTU/hr | 3 BTU/hr |
| | NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour. | | |
| Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) | Sound Power (L _{WAd} , bels) | Sound Pressure (L _{pAm} , decibels) | |
| Typically Configured – Idle | 3.3 | 24 | |
| Fixed Disk – Random writes | 3.3 | 23 | |
| Longevity and Upgrading | This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to “5” years after the end of production. | | |
| Batteries | This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight Batterv size: CR2032 (coin cell) | | |

Features

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| | Battery type: Lithium | | |
| Additional Information | <ul style="list-style-type: none"> • This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • This product is in compliance with the IEEE 1680 (EPEAT) standard at the <gold> level in the U.S. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains 0% post-consumer recycled plastic (by wt.) • This product is 95.1% recycle-able when properly disposed of at end of life. | | |
| Packaging Materials | External: | PAPER/Corrugated | 145 g |
| | Internal: | PLASTIC/EPE (Expanded Polyethylene) | 288 g |
| | | PLASTIC/Polyethylene low density | 30 g |
| Material Usage | <p>This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):</p> <ul style="list-style-type: none"> • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBEBs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) | | |

Features

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| Packaging Usage | <p>HP follows these guidelines to decrease the environmental impact of product packaging:</p> <ul style="list-style-type: none"> • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. |
| End-of-life Management and Recycling | <p>HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.</p> <p>The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.</p> <p>Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf</p> |

HP EliteOne 800 G4 All-in-One Business PC

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| Eco-Label Certifications & declarations | <p>This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:</p> <ul style="list-style-type: none"> • IT ECO declaration • US ENERGY STAR® • EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options. | | |
| System Configuration | The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a Typically Configured Desktop. | | |
| Energy Consumption (in accordance with US ENERGY STAR® test method) | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 50Hz |
| Normal Operation (Short idle) | 21.984 | 22.242 | 21.696 |
| Normal Operation (Long idle) | 11.351 | 11.604 | 11.222 |
| Sleep | 4.108 | 4.119 | 3.988 |
| Off | 0.734 | 0.747 | 0.693 |
| NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the | | | |



Features

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| | applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system. | | |
| Heat Dissipation* | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 50Hz |
| Normal Operation (Short idle) | 74.9654 | 75.8452 | 73.9834 |
| Normal Operation (Long idle) | 38.7069 | 39.5696 | 38.267 |
| Sleep | 14.0083 | 14.0458 | 13.5991 |
| Off | 2.5029 | 2.5473 | 2.3631 |
| | NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour. | | |
| Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) | Sound Power (L _{WAd} , bels) | | Sound Pressure (L _{pAm} , decibels) |
| Typically Configured – Idle | 3.9 | | 28 |
| Fixed Disk – Random writes | 4.4 | | 33 |
| Longevity and Upgrading | <p>This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:</p> <p>Spare parts are available throughout the warranty period and or for up to “5” years after the end of production.</p> | | |
| Batteries | <p>This battery(s) in this product comply with EU Directive 2006/66/EC</p> <p>Batteries used in the product do not contain:</p> <p>Mercury greater the 1ppm by weight</p> <p>Cadmium greater than 20ppm by weight</p> <p>Battery size: CR2032 (coin cell)</p> <p>Battery type: Lithium</p> | | |
| Additional Information | <ul style="list-style-type: none"> • This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • This product is in compliance with the IEEE 1680 (EPEAT) standard at the <gold> level in the U.S. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains 0% post-consumer recycled plastic (by wt.) • This product is 95.1% recycle-able when properly disposed of at end of life. | | |
| Packaging Materials | External: | PAPER/Corrugated | |
| | Internal: | PLASTIC/EPE (Expanded Polyethylene) | |
| | | PLASTIC/Polyethylene low density | |
| Material Usage | <p>This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):</p> <ul style="list-style-type: none"> • Asbestos • Certain Azo Colorants | | |

Features

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| | <ul style="list-style-type: none"> • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) |
| Packaging Usage | <p>HP follows these guidelines to decrease the environmental impact of product packaging:</p> <ul style="list-style-type: none"> • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. |
| End-of-life Management and Recycling | <p>HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.</p> <p>The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.</p> <p>Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf</p> |

Features

HP EliteOne 800 G4 Touch All-in-One Business PC

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| Eco-Label Certifications & declarations | This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: <ul style="list-style-type: none">• IT ECO declaration• US ENERGY STAR®• EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options. | | |
| System Configuration | The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a Typically Configured Desktop. | | |
| Energy Consumption (in accordance with US ENERGY STAR® test method) | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 60Hz |
| Normal Operation (Short idle) | 21.98 W | 22.24W | 21.69 W |
| Normal Operation (Long idle) | 11.35 W | 11.60 W | 11.22W |
| Sleep | 4.10 W | 4.11 W | 3.98 W |
| Off | 0.73 W | 0.74 W | 0.69 W |
| | NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system. | | |
| Heat Dissipation* | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 60Hz |
| Normal Operation (Short idle) | 75 BTU/hr | 76 BTU/hr | 74 BTU/hr |
| Normal Operation (Long idle) | 39 BTU/hr | 40 BTU/hr | 38 BTU/hr |
| Sleep | 14 BTU/hr | 14 BTU/hr | 13 BTU/hr |
| Off | 2 BTU/hr | 2 BTU/hr | 2 BTU/hr |
| | NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour. | | |
| Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) | Sound Power (L _{WAd} , bels) | Sound Pressure (L _{pAm} , decibels) | |
| Typically Configured – Idle | 3.2 | 20 | |
| Fixed Disk – Random writes | 3.5 | 28 | |
| Longevity and Upgrading | This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to “5” years after the end of production. | | |
| Batteries | This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight Batterv size: CR2032 (coin cell) | | |

Features

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| | Battery type: Lithium | | |
| Additional Information | <ul style="list-style-type: none"> • This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • This product is in compliance with the IEEE 1680 (EPEAT) standard at the <gold> level in the U.S. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains 0% post-consumer recycled plastic (by wt.) • This product is 95.1% recycle-able when properly disposed of at end of life. | | |
| Packaging Materials | External: | PAPER/Corrugated | 1419 g |
| | Internal: | PLASTIC/EPE (Expanded Polyethylene) | 694 g |
| | | PLASTIC/Polyethylene low density | 94 g |
| Material Usage | <p>This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):</p> <ul style="list-style-type: none"> • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBEBs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) | | |
| Packaging Usage | <p>HP follows these guidelines to decrease the environmental impact of product packaging:</p> <ul style="list-style-type: none"> • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. | | |

Features

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| End-of-life Management and Recycling | <p>HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.</p> <p>The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.</p> <p>Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf</p> |
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HP EliteOne 800 G4 GPU Touch All-in-One Business PC

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| Eco-Label Certifications & declarations | <p>This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:</p> <ul style="list-style-type: none"> • IT ECO declaration • US ENERGY STAR® • EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options. | | |
| System Configuration | The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a Typically Configured Notebook. | | |
| Energy Consumption (in accordance with US ENERGY STAR® test method) | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 60Hz |
| Normal Operation (Short idle) | 21.98 W | 22.24W | 21.69 W |
| Normal Operation (Long idle) | 11.35 W | 11.60 W | 11.22W |
| Sleep | 4.10 W | 4.11 W | 3.98 W |
| Off | 0.73 W | 0.74 W | 0.69 W |
| | <p>NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.</p> | | |
| Heat Dissipation* | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 60Hz |
| Normal Operation (Short idle) | 75 BTU/hr | 76 BTU/hr | 74 BTU/hr |
| Normal Operation (Long idle) | 39 BTU/hr | 40 BTU/hr | 38 BTU/hr |
| Sleep | 14 BTU/hr | 14 BTU/hr | 13 BTU/hr |
| Off | 2 BTU/hr | 2 BTU/hr | 2 BTU/hr |
| | <p>NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.</p> | | |

Features

| Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) | Sound Power (L _{WAd} , bels) | Sound Pressure (L _{pAm} , decibels) | |
|--|---|---|--------|
| Typically Configured – Idle | 3.2 | 20 | |
| Fixed Disk – Random writes | 3.5 | 28 | |
| Longevity and Upgrading | This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to “5” years after the end of production. | | |
| Batteries | This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight Battery size: CR2032 (coin cell) Battery type: Lithium | | |
| Additional Information | <ul style="list-style-type: none">• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.• This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.• This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).• This product is in compliance with the IEEE 1680 (EPEAT) standard at the <gold> level in the U.S. See http://www.epeat.net for registration status by country. Search keyword generator on HP’s 3rd party option store for solar generator accessories at http://www.hp.com/go/options• Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.• This product contains 0% post-consumer recycled plastic (by wt.)• This product is 95.1% recycle-able when properly disposed of at end of life. | | |
| Packaging Materials | External: | PAPER/Corrugated | 1419 g |
| | Internal: | PLASTIC/EPE (Expanded Polyethylene) | 694 g |
| | | PLASTIC/Polyethylene low density | 94 g |
| Material Usage | This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): <ul style="list-style-type: none">• Asbestos• Certain Azo Colorants• Certain Brominated Flame Retardants – may not be used as flame retardants in plastics• Cadmium• Chlorinated Hydrocarbons• Chlorinated Paraffins• Formaldehyde• Halogenated Diphenyl Methanes• Lead carbonates and sulfates• Lead and Lead compounds• Mercuric Oxide Batteries• Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.• Ozone Depleting Substances• Polybrominated Biphenyls (PBBs)• Polybrominated Biphenyl Ethers (PBBEs) | | |

Features

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| | <ul style="list-style-type: none"> • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) |
| Packaging Usage | <p>HP follows these guidelines to decrease the environmental impact of product packaging:</p> <ul style="list-style-type: none"> • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. |
| End-of-life Management and Recycling | <p>HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.</p> <p>The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.</p> <p>Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html</p> <p>Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html</p> <p>ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf</p> |

Features

HP EliteOne 800 G4 Non-Touch All-in-One Business PC

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| Eco-Label Certifications & declarations | This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: <ul style="list-style-type: none">• IT ECO declaration• US ENERGY STAR®• EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options. | | |
| System Configuration | The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a Typically Configured Notebook. | | |
| Energy Consumption (in accordance with US ENERGY STAR® test method) | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 60Hz |
| Normal Operation (Short idle) | 21.98 W | 22.24W | 21.69 W |
| Normal Operation (Long idle) | 11.35 W | 11.60 W | 11.22W |
| Sleep | 4.10 W | 4.11 W | 3.98 W |
| Off | 0.73 W | 0.74 W | 0.69 W |
| | NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system. | | |
| Heat Dissipation* | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 60Hz |
| Normal Operation (Short idle) | 75 BTU/hr | 76 BTU/hr | 74 BTU/hr |
| Normal Operation (Long idle) | 39 BTU/hr | 40 BTU/hr | 38 BTU/hr |
| Sleep | 14 BTU/hr | 14 BTU/hr | 13 BTU/hr |
| Off | 2 BTU/hr | 2 BTU/hr | 2 BTU/hr |
| | NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour. | | |
| Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) | Sound Power (L _{WAd} , bels) | Sound Pressure (L _{pAm} , decibels) | |
| Typically Configured – Idle | 3.2 | 20 | |
| Fixed Disk – Random writes | 3.5 | 28 | |
| Longevity and Upgrading | This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to “5” years after the end of production. | | |
| Batteries | This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight Batterv size: CR2032 (coin cell) | | |

Features

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| | Battery type: Lithium | | |
| Additional Information | <ul style="list-style-type: none"> • This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • This product is in compliance with the IEEE 1680 (EPEAT) standard at the <gold> level in the U.S. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains 0% post-consumer recycled plastic (by wt.) • This product is 95.1% recycle-able when properly disposed of at end of life. | | |
| Packaging Materials | External: | PAPER/Corrugated | 1419 g |
| | Internal: | PLASTIC/EPE (Expanded Polyethylene) | 694 g |
| | | PLASTIC/Polyethylene low density | 94 g |
| Material Usage | <p>This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):</p> <ul style="list-style-type: none"> • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBEBs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) | | |
| Packaging Usage | <p>HP follows these guidelines to decrease the environmental impact of product packaging:</p> <ul style="list-style-type: none"> • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. | | |

Features

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| End-of-life Management and Recycling | <p>HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.</p> <p>The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.</p> <p>Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf</p> |
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HP EliteOne 800 G4 GPU Non-Touch All-in-One Business PC

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| Eco-Label Certifications & declarations | <p>This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:</p> <ul style="list-style-type: none"> • IT ECO declaration • US ENERGY STAR® • EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options. | | |
| System Configuration | The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a Typically Configured Notebook. | | |
| Energy Consumption (in accordance with US ENERGY STAR® test method) | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 60Hz |
| Normal Operation (Short idle) | 21.98 W | 22.24W | 21.69 W |
| Normal Operation (Long idle) | 11.35 W | 11.60 W | 11.22W |
| Sleep | 4.10 W | 4.11 W | 3.98 W |
| Off | 0.73 W | 0.74 W | 0.69 W |
| | <p>NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.</p> | | |
| Heat Dissipation* | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 60Hz |
| Normal Operation (Short idle) | 75 BTU/hr | 76 BTU/hr | 74 BTU/hr |
| Normal Operation (Long idle) | 39 BTU/hr | 40 BTU/hr | 38 BTU/hr |
| Sleep | 14 BTU/hr | 14 BTU/hr | 13 BTU/hr |
| Off | 2 BTU/hr | 2 BTU/hr | 2 BTU/hr |
| | <p>NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.</p> | | |

Features

| Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) | Sound Power (L _{WAd} , bels) | Sound Pressure (L _{pAm} , decibels) | |
|--|---|---|--------|
| Typically Configured – Idle | 3.2 | 20 | |
| Fixed Disk – Random writes | 3.5 | 28 | |
| Longevity and Upgrading | This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to “5” years after the end of production. | | |
| Batteries | This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the 1ppm by weight Cadmium greater than 20ppm by weight Battery size: CR2032 (coin cell) Battery type: Lithium | | |
| Additional Information | <ul style="list-style-type: none">• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.• This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.• This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).• This product is in compliance with the IEEE 1680 (EPEAT) standard at the <gold> level in the U.S. See http://www.epeat.net for registration status by country. Search keyword generator on HP’s 3rd party option store for solar generator accessories at http://www.hp.com/go/options• Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.• This product contains 0% post-consumer recycled plastic (by wt.)• This product is 95.1% recycle-able when properly disposed of at end of life. | | |
| Packaging Materials | External: | PAPER/Corrugated | 1419 g |
| | Internal: | PLASTIC/EPE (Expanded Polyethylene) | 694 g |
| | | PLASTIC/Polyethylene low density | 94 g |
| Material Usage | This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): <ul style="list-style-type: none">• Asbestos• Certain Azo Colorants• Certain Brominated Flame Retardants – may not be used as flame retardants in plastics• Cadmium• Chlorinated Hydrocarbons• Chlorinated Paraffins• Formaldehyde• Halogenated Diphenyl Methanes• Lead carbonates and sulfates• Lead and Lead compounds• Mercuric Oxide Batteries• Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.• Ozone Depleting Substances• Polybrominated Biphenyls (PBBs)• Polybrominated Biphenyl Ethers (PBEBs) | | |

Features

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| | <ul style="list-style-type: none"> • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBO) |
| Packaging Usage | <p>HP follows these guidelines to decrease the environmental impact of product packaging:</p> <ul style="list-style-type: none"> • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. |
| End-of-life Management and Recycling | <p>HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.</p> <p>The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.</p> <p>Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf</p> |

HP EliteDesk 800 G4 65W Desktop Mini Business PC

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| Eco-Label Certifications & declarations | <p>This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:</p> <ul style="list-style-type: none"> • IT ECO declaration • US ENERGY STAR® • EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. | | |
| System Configuration | The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook." | | |
| Energy Consumption (in accordance with US ENERGY STAR® test method) | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 60Hz |
| Normal Operation (Short idle) | 3.59 W | 3.64 W | 3.46 W |
| Normal Operation (Long idle) | 3.11 W | 3.14 W | 3.04 W |

Features

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| Sleep | 0.63 W | 0.67 W | 0.63 W |
| Off | 0.60 W | 0.64 W | 0.59 W |
| | Note: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family . HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system. | | |
| Heat Dissipation* | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 60Hz |
| Normal Operation (Short idle) | 12 BTU/hr | 12 BTU/hr | 12 BTU/hr |
| Normal Operation (Long idle) | 11 BTU/hr | 11 BTU/hr | 10 BTU/hr |
| Sleep | 2 BTU/hr | 2 BTU/hr | 2 BTU/hr |
| Off | 2 BTU/hr | 2 BTU/hr | 2 BTU/hr |
| | *NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour. | | |
| Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) | Sound Power (L _{WAd} , bels) | Sound Pressure (L _{pAm} , decibels) | |
| Typically Configured – Idle | 3.1 | 19 | |
| Fixed Disk – Random writes | 3.1 | 19 | |
| Longevity and Upgrading | This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: <ul style="list-style-type: none">• 3 USB ports• 1 PC card slot (type I/II)• 1 ExpressCard/54 slot• 1 IEEE 1394 Port• 2 SODIMM memory slots• Optional expansion base docking station• 1 multi-bay II storage port• Interchangeable HDD Spare parts are available throughout the warranty period and or for up to “5” years after the end of production. | | |
| Batteries | This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight Battery size: CR2032 (coin cell) Battery type: Lithium | | |

Features

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| Additional Information | <ul style="list-style-type: none"> This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive – 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680 (EPEAT[®]) standard at the gold level, see www.epeat.net Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. This product contains 24.1% post-consumer recycled plastic (by wt.) This product is 91.7% recycle-able when properly disposed of at end of life. | | |
| Packaging Materials | External: | PAPER/Corrugated | 322 g |
| | Internal: | PLASTIC/Polyethylene Expanded - EPE | 32 g |
| | | PLASTIC/Polyethylene High density - HDPE | 5 g |
| | The Plastic packaging material is made from 0% recycled content. | | |
| | The paper packaging materials contains at least 25% recycled content. | | |
| Material Usage | <p>This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):</p> <ul style="list-style-type: none"> Asbestos Certain Azo Colorants Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyls (PBBs) Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) | | |

Features

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| Packaging Usage | <p>HP follows these guidelines to decrease the environmental impact of product packaging:</p> <ul style="list-style-type: none"> • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. |
| End-of-life Management and Recycling | <p>Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.</p> <p>The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.</p> |
| HP, Inc. Corporate Environmental Information | <p>For more information about HP's commitment to the environment:</p> <p>Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html</p> <p>Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html</p> <p>ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf</p> |

Features

HP EliteDesk 800 G4 35W Desktop Mini Business PC

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| Eco-Label Certifications & declarations | This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: <ul style="list-style-type: none">• IT ECO declaration• US ENERGY STAR®• EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. | | |
| System Configuration | The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a “Typically Configured Notebook.” | | |
| Energy Consumption (in accordance with US ENERGY STAR® test method) | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 60Hz |
| Normal Operation (Short idle) | 3.59 W | 3.64 W | 3.46 W |
| Normal Operation (Long idle) | 3.11 W | 3.14 W | 3.04 W |
| Sleep | 0.63 W | 0.67 W | 0.63 W |
| Off | 0.60 W | 0.64 W | 0.59 W |
| | Note: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family . HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system. | | |
| Heat Dissipation* | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 60Hz |
| Normal Operation (Short idle) | 12 BTU/hr | 12 BTU/hr | 12 BTU/hr |
| Normal Operation (Long idle) | 11 BTU/hr | 11 BTU/hr | 10 BTU/hr |
| Sleep | 2 BTU/hr | 2 BTU/hr | 2 BTU/hr |
| Off | 2 BTU/hr | 2 BTU/hr | 2 BTU/hr |
| | *NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour. | | |
| Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) | Sound Power (L_{WAd}, bels) | Sound Pressure (L_{pAm}, decibels) | |
| Typically Configured – Idle | 2.9 | 19 | |
| Fixed Disk – Random writes | 2.9 | 19 | |
| Longevity and Upgrading | This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: <ul style="list-style-type: none">• 3 USB ports• 1 PC card slot (type I/II)• 1 ExpressCard/54 slot• 1 IEEE 1394 Port• 2 SODIMM memory slots | | |

Features

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|-------------------------------|---|--|-------|
| | <ul style="list-style-type: none"> • Optional expansion base docking station • 1 multi-bay II storage port • Interchangeable HDD <p>Spare parts are available throughout the warranty period and or for up to “5” years after the end of production.</p> | | |
| Batteries | <p>This battery(s) in this product comply with EU Directive 2006/66/EC</p> <p>Batteries used in the product do not contain:</p> <ul style="list-style-type: none"> Mercury greater the 1ppm by weight Cadmium greater than 20ppm by weight <p>Battery size: CR2032 (coin cell)</p> <p>Battery type: Lithium</p> | | |
| Additional Information | <ul style="list-style-type: none"> • This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive – 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • This product is in compliance with the IEEE 1680 (EPEAT[®]) standard at the gold level, see www.epeat.net • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains 24.1% post-consumer recycled plastic (by wt.) • This product is 91.7% recycle-able when properly disposed of at end of life. | | |
| Packaging Materials | External: | PAPER/Corrugated | 322 g |
| | Internal: | PLASTIC/Polyethylene Expanded - EPE | 32 g |
| | | PLASTIC/Polyethylene High density - HDPE | 5 g |
| | The Plastic packaging material is made from 0% recycled content. | | |
| | The paper packaging materials contains at least 25% recycled content. | | |
| Material Usage | <p>This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):</p> <ul style="list-style-type: none"> • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) | | |

Features

| | |
|---|--|
| | <ul style="list-style-type: none"> • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) |
| Packaging Usage | <p>HP follows these guidelines to decrease the environmental impact of product packaging:</p> <ul style="list-style-type: none"> • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. |
| End-of-life Management and Recycling | <p>Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.</p> <p>The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.</p> |
| HP, Inc. Corporate Environmental Information | <p>For more information about HP's commitment to the environment:</p> <p>Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html</p> <p>Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html</p> <p>ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf</p> |

Features

HP EliteDesk 800 G4 95W Desktop Mini Business PC

| | | | |
|--|---|--|---------------------|
| Eco-Label Certifications & declarations | This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: <ul style="list-style-type: none">• IT ECO declaration• US ENERGY STAR®• EPEAT[®] Gold registered in the United States. See http://www.epeat.net for registration status in your country. | | |
| System Configuration | The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a “Typically Configured Notebook.” | | |
| Energy Consumption (in accordance with US ENERGY STAR® test method) | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 60Hz |
| Normal Operation (Short idle) | 3.59 W | 3.64 W | 3.46 W |
| Normal Operation (Long idle) | 3.11 W | 3.14 W | 3.04 W |
| Sleep | 0.63 W | 0.67 W | 0.63 W |
| Off | 0.60 W | 0.64 W | 0.59 W |
| | Note: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family . HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system. | | |
| Heat Dissipation* | 115VAC, 60Hz | 230VAC, 50Hz | 100VAC, 60Hz |
| Normal Operation (Short idle) | 12 BTU/hr | 12 BTU/hr | 12 BTU/hr |
| Normal Operation (Long idle) | 11 BTU/hr | 11 BTU/hr | 10 BTU/hr |
| Sleep | 2 BTU/hr | 2 BTU/hr | 2 BTU/hr |
| Off | 2 BTU/hr | 2 BTU/hr | 2 BTU/hr |
| | *NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour. | | |
| Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) | Sound Power (L _{Wad} , bels) | Sound Pressure (L _{pAm} , decibels) | |
| Typically Configured – Idle | 2.8 | 19 | |
| Fixed Disk – Random writes | 2.8 | 19 | |
| Longevity and Upgrading | This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: <ul style="list-style-type: none">• 3 USB ports• 1 PC card slot (type I/II)• 1 ExpressCard/54 slot• 1 IEEE 1394 Port• 2 SODIMM memory slots | | |

Features

| | | | |
|-------------------------------|---|--|-------|
| | <ul style="list-style-type: none"> • Optional expansion base docking station • 1 multi-bay II storage port • Interchangeable HDD <p>Spare parts are available throughout the warranty period and or for up to “5” years after the end of production.</p> | | |
| Batteries | <p>This battery(s) in this product comply with EU Directive 2006/66/EC</p> <p>Batteries used in the product do not contain:</p> <ul style="list-style-type: none"> Mercury greater the 1ppm by weight Cadmium greater than 20ppm by weight <p>Battery size: CR2032 (coin cell)</p> <p>Battery type: Lithium</p> | | |
| Additional Information | <ul style="list-style-type: none"> • This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive – 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • This product is in compliance with the IEEE 1680 (EPEAT[®]) standard at the gold level, see www.epeat.net • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains 24.1% post-consumer recycled plastic (by wt.) • This product is 91.7% recycle-able when properly disposed of at end of life. | | |
| Packaging Materials | External: | PAPER/Corrugated | 322 g |
| | Internal: | PLASTIC/Polyethylene Expanded - EPE | 32 g |
| | | PLASTIC/Polyethylene High density - HDPE | 5 g |
| | The Plastic packaging material is made from 0% recycled content. | | |
| | The paper packaging materials contains at least 25% recycled content. | | |
| Material Usage | <p>This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):</p> <ul style="list-style-type: none"> • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) | | |

Features

| | |
|---|--|
| | <ul style="list-style-type: none"> • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) |
| Packaging Usage | <p>HP follows these guidelines to decrease the environmental impact of product packaging:</p> <ul style="list-style-type: none"> • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. |
| End-of-life Management and Recycling | <p>Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.</p> <p>The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.</p> |
| HP, Inc. Corporate Environmental Information | <p>For more information about HP's commitment to the environment:</p> <p>Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html</p> <p>Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html</p> <p>ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf</p> |

SERVICE AND SUPPORT

HP EliteDesk 800 G4 Tower Business PC

On-site Warranty¹⁵: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day¹⁶ service for parts and labor and includes free support 24 x 7¹⁷. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: <http://www.hp.com/go/cpc>.¹⁸

15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.

16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.

18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

HP EliteDesk 800 G4 Small Form Factor Business PC

On-site Warranty¹⁵: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day¹⁶ service for parts and labor and includes free support 24 x 7¹⁷. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: <http://www.hp.com/go/cpc>.¹⁸

15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.

16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.

18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

Features

HP EliteDesk 800 G4 Desktop Mini Business PC

On-site Warranty¹⁵: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day¹⁶ service for parts and labor and includes free support 24 x 7¹⁷. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: <http://www.hp.com/go/cpc>.¹⁸

15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.

16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.

18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

HP EliteOne 800 G4 All-in-One Business PC

On-site Warranty¹⁵: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day¹⁶ service for parts and labor and includes free support 24 x 7¹⁷. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: <http://www.hp.com/go/cpc>.¹⁸

15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.

16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.

18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

Technical Specifications

CERTIFICATION AND COMPLIANCE

Energy Efficiency Compliance

ENERGY STAR® certified; EPEAT® Gold ¹⁹

19. EPEAT® registered where applicable. EPEAT registration varies by country. See <http://www.epeat.net> for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at <http://www.hp.com/go/options>.

PROCESSORS

Intel® 8th Generation Core™ Processors

All HP EliteDesk 800 G4 Business PC models featuring this technology include processors that are part of the Intel® Stable Image Platform Program (SIPP) designed to ensure the stability promise inherent in the value proposition of the HP EliteDesk and EliteOne 800 G4 Business PC.

Intel® Advanced Management Technology (AMT) v12 – An advanced set of remote management features and functionality which provides network administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 12 includes the following advanced management functions:

- Support for configuration of Intel AMT 12.0 new capabilities
- No reset after provisioning
- Support changes to BIOS table 130
- Support for Microsoft Windows Server 2012 R2
- Support for New Microsoft SQL Server Versions including Standard and Enterprise editions
- Support for Intel SSD Prop 2500 Series
- Support for Intel Enterprise Digital Fence
- The Platform Discovery Utility can now discover these additional Intel products:
- Intel SSD Pro 2500 Series; Enterprise Digital Fence
- Intel Identity Protection Technology with One Time Password; Public Key Infrastructure; Multi Factor Authentication
- Intel Identity Protection Technology with Intel WiGig
- New Profile Editor and Profile Editor Plugin Interface
- New Required Permissions for Solutions Framework

Technical Specifications

DISPLAY PANEL SPECIFICATIONS

23.8" diagonal IPS widescreen WLED backlit anti-glare LCD (1920 x 1080) non-touch or optional touch

Projected Capacitive Touch supports up to 10 touch-points

| | |
|---|--|
| Type | IPS WLED Backlit LCD |
| Active area (mm) | 527.04 x 296.46 |
| Native Resolution (HxV) | 1920 x 1080 |
| Refresh Rate | 60 Hz @ 1920 x 1080 |
| Aspect ratio | 16:09 |
| Pixel pitch (HxV)(mm) | 0.2745 x 0.2745 |
| Contrast ratio (typical) | 1000:01:00 |
| Brightness (typical) | 250nits |
| Viewing angle (typical) (HxV) | 178 ° x 178 ° |
| Backlight lamp life (to half brightness) | 30,000 hours minimum |
| Color support | Up to 16.7 million colors with the use of FRC technology |
| Color gamut (typical) | NTSC 72% |
| Anti-glare | Yes* |
| Response Time | 14ms (Typical) |
| Default color temperature | Warm (6500K) |

1. All performance specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

2. For All in One only

Intel® HD Graphics (integrated)

| | | |
|---------------------------------|--|---|
| Adjustable Height Stand: | Height - Vertical/Landscape Adjustment | 101mm (±2 mm) |
| | Portrait Adjustment | 54mm (±2 mm) |
| | Tilt Angle | -5° to +20° (±3°) in landscape and portrait |
| | Rotation (Swivel) | 90° (±1°) |
| | Pivot | Clockwise 90° |
| Recline Stand: | Height - Vertical Adjustment | 178 mm (±2 mm) |
| | Tilt Angle | -5° to +65° (+/-3°) |
| | Rotation (swivel) | 360° swivel |

Technical Specifications

GRAPHICS

HP EliteDesk 800 G4 Desktop Mini Business PC

Intel® HD Graphics (integrated)

VGA Controller

Integrated

DisplayPort™ 1.2

Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 3 displays connected to any output controlled by Intel® Graphics

HDMI (optional)

Supports HDMI 2.0a features

Supports HDCP 2.2

Supports audio over HDMI

VGA (optional)

VGA output

USB-C™ DP Alt Mode (optional)

DisplayPort over the optional USB-C™ module

Memory

The actual amount of maximum graphics memory can be >4GB. System memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.

Maximum Color Depth

up to 10 bits/color

HEVC 10b Enc/Dec HW

VP9 10b Dec HW

Graphics/Video API Support

HDR

Rec. 2020

DX12

Max. Resolution (VGA)

2048 x 1536@60Hz

Max. Resolution (HDMI)

4096 x 2160@60Hz

Max. Resolution (DP)

4096 x 2160@60Hz

AMD® Radeon™ RX 560

Architecture

Discrete GPU

AMD® GPU drives the integrated panel and all of the graphics output ports

DisplayPort

Multimode capable; supports HDCP, HDR, Display Port Audio (6 streams max), DisplayPort HBR3 link rates and Multi-Stream Technology for a maximum of 5 displays (including the integrated panel and all attached displays)

HDMI

Supports HDMI 2.0b features

Supports HDCP 2.2, HDR

Memory

4GByte, 128bit wide GDDR5

Maximum Color Depth

up to 12 bits/color

Graphics/Video API Support

DirectX 12

OpenCL 2.0

OpenGL 4.5

AMD® Unified Video Decoder (UVD)

Rear I/O connector

1 DP

Max. Resolution (VGA)

2048 x 1536@60Hz

Max. Resolution (HDMI)

4096 x 2160@60Hz

Max. Resolution (DP)

5120 x 2880@60Hz

Technical Specifications

HP EliteDesk 800 G4 Tower Business PC

Intel® UHD Graphics (integrated)

VGA Controller

Integrated

DisplayPort™ 1.2

Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 3 displays connected to any output controlled by Intel® Graphics

HDMI (optional)

Supports HDMI 2.0a features

Supports HDCP 2.2

Supports BT2020 and HDR playback (7th Gen processors only)

VGA (optional)

VGA output

USB-C™ DP Alt Mode (optional)

DisplayPort over the optional USB-C™ module

Memory

The actual amount of maximum graphics memory can be >4GB. System memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.

Maximum Color Depth

up to 10 bits/color

HEVC 10b Enc/Dec HW

VP9 10b Dec HW

Graphics/Video API Support

HDR

Rec. 2020

DX12

640x480 60 Hz 640x480 67Hz

640x480 72Hz

640x480 75Hz

720x400 70Hz

800x600 60Hz

800x600 75Hz

1024x768 60Hz

1024x768 75Hz

1280x960 60Hz

1280x720 60Hz

1280x1024 60Hz

1280x1024 75Hz

1440x900 60Hz

1440x900 75Hz

1680x1050 60Hz

1920x1080 60Hz

3440x1440 60Hz (Native Resolution)

3440x1440 30Hz

Max. Resolution (VGA)

2048 x 1536@60Hz

Max. Resolution (HDMI)

4096 x 2160@60Hz

Max. Resolution (DP)

4096 x 2160@60Hz

Technical Specifications

NVIDIA® GeForce® GT730 2GB DP DVI PCIe x8 GFX

| | |
|-------------------------------------|--|
| Engine Clock | 902 MHz |
| Memory Clock | 1250 MHz |
| Memory Size(width) | 2 GB (64-bit) |
| Memory Type | 256Mx32 GDDR5 |
| Max. Resolution(DVI) | 2560 x 1600 x 30 bpp @ 60Hz (Dual Link) |
| Max. Resolution(DP) | 4096 x 2160 x 24 bpp @ 60 Hz (DP1.2) |
| Multi Display Support | Up to 2 displays |
| HDCP Compliance | Yes |
| Rear I/O connectors(bracket) | DL DVI-I + DP |
| Cooling(active/passive) | Active fan-sink (Active cooling with dynamic speed) |
| Total power consumption(W) | 35 W |
| PCB form-factor with bracket | 2-pin fan connector for fan sink power/speed control |

NVIDIA® GeForce® GTX 1060 3 GB Graphics Card

| | |
|-------------------------------------|---|
| Engine Clock | 1506 MHz |
| Memory Clock | 4004 MHz |
| Memory Size(width) | 3 GB(192-bit) |
| Memory Type | 128M x 32 GDDR5 |
| Max. Resolution(DVI) | 2560x1600@60Hz |
| Max. Resolution(HDMI) | 4096x2160@60Hz |
| Max. Resolution(DP) | 5120x3200@60Hz |
| Multi Display Support | 4 displays |
| HDCP Compliance | Yes |
| Rear I/O connectors(bracket) | DVI-D+HDMI+DPx3 |
| Cooling(active/passive) | Active fan-sink (Active cooling with dynamic speed) |
| Total power consumption(W) | <120W |
| PCB form-factor with bracket | ATX (Full height) PCB with ATX dual slot bracket |

AMD® Radeon™ RX550 4 GB FH PCIe x16

| | |
|-------------------------------------|---|
| Engine Clock | 1183MHz |
| Memory Clock | 7 Gbps |
| Memory Size(width) | 4 GB(128-bit) |
| Memory Type | GDDR5 |
| Max. Resolution(HDMI) | 4096x2160 @ 60Hz |
| Max. Resolution(DP) | 5120x2880 @ 60Hz |
| Multi Display Support | 3 displays |
| HDCP Compliance | Yes |
| Rear I/O connectors(bracket) | HDMI, DPx2 |
| Cooling(active/passive) | Active fan-sink (Active cooling with dynamic speed) |
| Total power consumption(W) | <62W |
| PCB form-factor with bracket | ATX (Full height) PCB with ATX single slot bracket |

Technical Specifications

AMD® Radeon™ RX580 4 GB FH PCIe x16

| | |
|-------------------------------------|---|
| Engine Clock | 1266 MHz |
| Memory Clock | 8gb/s |
| Memory Size(width) | 4 GB (256-bit) |
| Memory Type | 128M x 32 GDDR5 |
| Max. Resolution(HDMI) | 4096x2160@60Hz |
| Max. Resolution(DP) | 5120x3200@60Hz |
| Multi Display Support | 4 displays |
| HDCP Compliance | Yes |
| Rear I/O connectors(bracket) | DP*3 + HDMI |
| Cooling(active/passive) | Active fan-sink (Active cooling with dynamic speed) |
| Total power consumption(W) | <150W |
| PCB form-factor with bracket | ATX (Full height) PCB with ATX dual slot bracket |

AMD® Radeon™ RX580 8GB GDDR5 Graphics Card

| | |
|-------------------------------------|---|
| Engine Clock | 1266 MHz |
| Memory Clock | 4000 MHz |
| Memory Size(width) | 8 GB (256-bit) |
| Memory Type | 256M x 32 GDDR5 |
| Max. Resolution(HDMI) | 4096x2160@60Hz |
| Max. Resolution(DP) | 5120x3200@60Hz |
| Multi Display Support | 4 displays |
| HDCP Compliance | Yes |
| Rear I/O connectors(bracket) | HDMI + DPx3 |
| Cooling(active/passive) | Active fan-sink (Active cooling with dynamic speed) |
| Total power consumption(W) | <150W |
| PCB form-factor with bracket | ATX (Full height) PCB with ATX dual slot bracket |

NVIDIA® GeForce® RTX 2080 8GB GDDR6

| | |
|--------------------------------------|---|
| Engine Clock | 1710 MHz |
| Memory Clock | 7000 MHz |
| Memory Size(width) | 8GB (256-bit) |
| Memory Type | 256M x 32 GDDR6 |
| Max. Resolution(Virtual Link) | 3840 x 2160@60Hz |
| Max. Resolution(HDMI) | 4096 x 2160@60Hz |
| Max. Resolution(DP) | 7680 x 4320@60Hz |
| Multi Display Support | 4 displays |
| HDCP Compliance | Yes |
| Rear I/O connectors(bracket) | DPx3 + HDMI + Virtual Link |
| Cooling(active/passive) | Active fan-sink (Active cooling with dynamic speed) |
| Total power consumption(W) | <250W |
| PCB form-factor with bracket | ATX (Full height) PCB with ATX dual slot bracket |

Technical Specifications

NVIDIA® Quadro P620 2GB Graphics Card

| | |
|-------------------------------------|---|
| Engine Clock | 1354 MHz |
| Memory Clock | 2500 MHz |
| Memory Size(width) | 2GB (128-bit) |
| Memory Type | 128M x 32 GDDR5 |
| Max. Resolution(DP) | 5120x2880@60Hz |
| Multi Display Support | 4 displays |
| HDCP Compliance | Yes |
| Rear I/O connectors(bracket) | mDPx4 |
| Cooling(active/passive) | Active fan-sink (Active cooling with dynamic speed) |
| Total power consumption(W) | <40W |
| PCB form-factor with bracket | LP PCB with LP bracket |

NVIDIA® Quadro P400 2GB Graphics Card

| | |
|-------------------------------------|---|
| Engine Clock | 1252 MHz |
| Memory Clock | 2000 MHz |
| Memory Size(width) | 2GB (64-bit) |
| Memory Type | 256M x 32 GDDR5 |
| Max. Resolution(DP) | 5120x2880@60Hz |
| Multi Display Support | 3 displays |
| HDCP Compliance | Yes |
| Rear I/O connectors(bracket) | mDPx3 |
| Cooling(active/passive) | Active fan-sink (Active cooling with dynamic speed) |
| Total power consumption(W) | <30W |
| PCB form-factor with bracket | LP PCB with LP bracket |

AMD® Radeon™ R7 430 2GB VGA+DP Graphics Card

| | |
|-------------------------------------|---|
| Engine Clock | 780 MHz |
| Memory Clock | 1100 MHz |
| Memory Size(width) | 2 GB(128-bit) |
| Memory Type | 128M x 32 GDDR5 |
| Max. Resolution(HDMI) | 2048x1536 |
| Max. Resolution(DP) | 4096x2160@60Hz |
| Multi Display Support | 2 displays |
| HDCP Compliance | Yes |
| Rear I/O connectors(bracket) | VGA+DP |
| Cooling(active/passive) | Active fan-sink (Active cooling with dynamic speed) |
| Total power consumption(W) | <50W |
| PCB form-factor with bracket | LP PCB with FH/LP bracket |

Technical Specifications

AMD® Radeon™ R7 430 2GB GDDR5 2DP Graphics Card

| | |
|-------------------------------------|---|
| Engine Clock | 780 MHz |
| Memory Clock | 1100 MHz |
| Memory Size(width) | 2 GB(64-bit) |
| Memory Type | 256M x 32 GDDR5 |
| Max. Resolution(DP) | 4096x2160@60Hz |
| Multi Display Support | 2 displays |
| HDCP Compliance | yes |
| Rear I/O connectors(bracket) | DPx2 |
| Cooling(active/passive) | Active fan-sink (Active cooling with dynamic speed) |
| Total power consumption(W) | <50W |
| PCB form-factor with bracket | LP PCB with FH/LP bracket |

AMD® Radeon™ R7 430 2GB 2DP Graphics Card

| | |
|-------------------------------------|---|
| Engine Clock | 780 MHz |
| Memory Clock | 1100 MHz |
| Memory Size(width) | 2 GB(128-bit) |
| Memory Type | 128M x 32 GDDR5 |
| Max. Resolution(DP) | 4096x2160@60Hz |
| Multi Display Support | 2 displays |
| HDCP Compliance | Yes |
| Rear I/O connectors(bracket) | 2DP |
| Cooling(active/passive) | Active fan-sink (Active cooling with dynamic speed) |
| Total power consumption(W) | <50W |
| PCB form-factor with bracket | LP PCB with FH/LP bracket |

Technical Specifications

HP EliteDesk 800 G4 Small Form Factor Business PC

Intel® HD Graphics (integrated)

| | |
|--------------------------------------|---|
| VGA Controller | Integrated |
| DisplayPort™ 1.2 | Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 3 displays connected to any output controlled by Intel® Graphics |
| HDMI (optional) | Supports HDMI 2.0a features Supports HDCP 2.2 Supports audio over HDMI |
| VGA (optional) | VGA Output |
| USB-C™ DP Alt Mode (optional) | DisplayPort over the optional USB-C™ module |
| Memory | The actual amount of maximum graphics memory can be >4GB. System memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use. |
| Maximum Color Depth | up to 10 bits/color HEVC 10b Enc/Dec HW VP9 10b Dec HW |
| Graphics/Video API Support | HDR Rec. 2020 DX12 |
| Max. Resolution (VGA) | 2048 x 1536@60Hz |
| Max. Resolution (HDMI) | 4096 x 2160@60Hz |
| Max. Resolution (DP) | 4096 x 2160@60Hz |

AMD® Radeon™ R7 430 2 GB VGA+DP Graphics Card

| | |
|-------------------------------------|---|
| Engine Clock | 780 MHz |
| Memory Clock | 1100 MHz |
| Memory Size(width) | 2 GB(128-bit) |
| Memory Type | 128M x 32 GDDR5 |
| Max. Resolution(VGA) | 2048x1536 |
| Max. Resolution(DP) | 4096x2160@60Hz |
| Multi Display Support | 2 displays |
| HDCP Compliance | Yes |
| Rear I/O connectors(bracket) | VGA+DP |
| Cooling(active/passive) | Active fan-sink (Active cooling with dynamic speed) |
| Total power consumption(W) | <50W |
| PCB form-factor with bracket | LP PCB with FH/LP bracket |

AMD® Radeon™ R7 430 2GB GDDR5 DP+VGA Graphics Card

| | |
|-------------------------------------|-----------------|
| Engine Clock | 780 MHz |
| Memory Clock | 1100 MHz |
| Memory Size(width) | 2 GB(64-bit) |
| Memory Type | 256M x 32 GDDR5 |
| Max. Resolution(VGA) | 2048x1536 |
| Max. Resolution(DP) | 4096x2160@60Hz |
| Multi Display Support | 2 displays |
| HDCP Compliance | yes |
| Rear I/O connectors(bracket) | DP+VGA |

Technical Specifications

| | |
|-------------------------------------|---|
| Cooling(active/passive) | Active fan-sink (Active cooling with dynamic speed) |
| Total power consumption(W) | <50W |
| PCB form-factor with bracket | LP PCB with FH/LP bracket |

AMD® Radeon™ R7 430 2GB GDDR5 2DP Graphics Card

| | |
|-------------------------------------|---|
| Engine Clock | 780 MHz |
| Memory Clock | 1100 MHz |
| Memory Size(width) | 2 GB(64-bit) |
| Memory Type | 256M x 32 GDDR5 |
| Max. Resolution(DP) | 4096x2160@60Hz |
| Multi Display Support | 2 displays |
| HDCP Compliance | yes |
| Rear I/O connectors(bracket) | DPx2 |
| Cooling(active/passive) | Active fan-sink (Active cooling with dynamic speed) |
| Total power consumption(W) | <50W |
| PCB form-factor with bracket | LP PCB with FH/LP bracket |

AMD® Radeon™ R7 430 2 GB 2DP Graphics Card

| | |
|-------------------------------------|---|
| Engine Clock | 780 MHz |
| Memory Clock | 1100 MHz |
| Memory Size(width) | 2GB(128-bit) |
| Memory Type | 128M x 32 GDDR5 |
| Max. Resolution(DP) | 4096x2160@60Hz |
| Multi Display Support | 2 displays |
| HDCP Compliance | Yes |
| Rear I/O connectors(bracket) | 2DP |
| Cooling(active/passive) | Active fan-sink (Active cooling with dynamic speed) |
| Total power consumption(W) | <50W |
| PCB form-factor with bracket | LP PCB with FH/LP bracket |

NVIDIA® GeForce® GT730 2GB DP DVI PCIe x8 GFX

| | |
|-------------------------------------|--|
| Engine Clock | 902 MHz |
| Memory Clock | 1250 MHz |
| Memory Size(width) | 2 GB (64-bit) |
| Memory Type | 256Mx32 GDDR5 |
| Max. Resolution(DVI) | 2560 x 1600 x 30 bpp @ 60Hz (Dual Link) |
| Max. Resolution(DP) | 4096 x 2160 x 24 bpp @ 60 Hz (DP1.2) |
| Multi Display Support | Up to 2 displays |
| HDCP Compliance | Yes |
| Rear I/O connectors(bracket) | DL DVI-I + DP |
| Cooling(active/passive) | Active fan-sink (Active cooling with dynamic speed) |
| Total power consumption(W) | 35 W |
| PCB form-factor with bracket | 2-pin fan connector for fan sink power/speed control |

Technical Specifications

HP EliteOne 800 G4 All-in-One Business PC

Intel® UHD Graphics (integrated)

VGA Controller

Integrated

DisplayPort™ 1.2

Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 3 displays (including the integrated panel and all attached displays)

HDMI

Supports HDMI 2.0a features

Supports HDCP 2.2

Supports audio over HDMI

Memory

The actual amount of maximum graphics memory can be >4GB. System memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.

Maximum Color Depth

up to 10 bits/color

HEVC 10b Enc/Dec HW

VP9 10b Dec HW

Graphics/Video API Support

HDR

Rec. 2020

DX12

Max. Resolution (VGA)

2048 x 1536@60Hz

Max. Resolution (HDMI)

4096 x 2160@60Hz

Max. Resolution (DP)

4096 x 2160@60Hz

AMD® Radeon™ RX 560

Architecture

Discrete GPU

AMD® GPU drives the integrated panel and all of the graphics output ports

DisplayPort

Multimode capable; supports HDCP, HDR, Display Port Audio (6 streams max), DisplayPort HBR3 link rates and Multi-Stream Technology for a maximum of 5 displays (including the integrated panel and all attached displays)

HDMI

Supports HDMI 2.0b features

Supports HDCP 2.2, HDR

Memory

4GByte, 128bit wide GDDR5

Maximum Color Depth

up to 12 bits/color

Graphics/Video API Support

DirectX 12

OpenCL 2.0

OpenGL 4.5

AMD® Unified Video Decoder (UVD)

Rear I/O connector

1 DP

Max. Resolution (VGA)

2048 x 1536@60Hz

Max. Resolution (HDMI)

4096 x 2160@60Hz

Max. Resolution (DP)

5120 x 2880@60Hz

Technical Specifications

STORAGE

500 GB 7200RPM 3.5in SATA HDD

| | |
|------------------------------|--------------------------------|
| Capacity | 500 GB |
| Rotational Speed | 7,200 rpm |
| Interface | SATA 6.0 Gb/s |
| Buffer Size | 16 MB |
| Logical Blocks | 976,773,168 |
| Seek Time | 11 ms (Average) |
| Height | 1 in/2.54 cm |
| | Media diameter: 3.5 in/8.89 cm |
| Width | Physical size: 4 in/10.2 cm |
| Operating Temperature | 41° to 131° F (5° to 55° C) |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1 TB 7200RPM 3.5in SATA HDD

| | |
|------------------------------|--------------------------------|
| Capacity | 1 TB |
| Rotational Speed | 7,200 rpm |
| Interface | SATA 6 Gb/s |
| Buffer Size | 32 MB |
| Logical Blocks | 1,953,525,168 |
| Seek Time | 11 ms (Average) |
| Height | 1 in/2.54 cm |
| | Media diameter: 3.5 in/8.89 cm |
| Width (nominal) | Physical size: 4 in/10.2 cm |
| Operating Temperature | 41° to 131° F (5° to 55° C) |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2 TB 7200RPM 3.5in SATA HDD

| | |
|------------------------------|-----------------------------|
| Capacity | 2 TB |
| Rotational Speed | 7,200 rpm |
| Interface | SATA 6 Gb/s |
| Buffer Size | 64 MB |
| Logical Blocks | 1,953,525,168 |
| Seek Time | 11 ms (Average) |
| Height | 1.028 in/26.11 mm |
| Width (nominal) | 4.0 in/101.6 mm |
| Operating Temperature | 41° to 131° F (5° to 55° C) |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications

500 GB 7200RPM 2.5in SATA HDD

| | |
|------------------------------|-----------------------------|
| Capacity | 500 GB |
| Rotational Speed | 7,200 rpm |
| Interface | SATA 6 Gb/s |
| Buffer Size | 16 MB |
| Logical Blocks | 976,773,168 |
| Seek Time | 12 ms (Average) |
| Height | 0.267 in/6.8 mm (nominal) |
| Width (nominal) | 2.75 in/70 mm (nominal) |
| Operating Temperature | 41° to 131° F (5° to 55° C) |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1 TB 7200RPM 2.5in SATA HDD

| | |
|------------------------------|-----------------------------|
| Capacity | 1 TB |
| Rotational Speed | 7,200 rpm |
| Interface | SATA 6 Gb/s |
| Buffer Size | 32 MB |
| Logical Blocks | 1,953,525,168 |
| Seek Time | 12 ms (Average) |
| Height | 0.374 in/9.5 mm (nominal) |
| Width (nominal) | 2.75 in/70 mm (nominal) |
| Operating Temperature | 41° to 131° F (5° to 55° C) |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2 TB 5400RPM 2.5in SATA HDD

| | |
|------------------------------|-----------------------------|
| Capacity | 2 TB |
| Rotational Speed | 5,400 rpm |
| Interface | SATA 6 Gb/s |
| Buffer Size | 128 MB |
| Logical Blocks | 3,907,050,336 |
| Seek Time | 12 ms (Average) |
| Height | 0.374 in/9.5 mm (nominal) |
| Width (nominal) | 2.75 in/70 mm (nominal) |
| Operating Temperature | 41° to 131° F (5° to 55° C) |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications

500 GB 7200RPM 2.5in Self Encrypted OPAL2 SATA HDD

| | |
|------------------------------|---|
| Capacity | 500 GB |
| Architecture | Self-Encrypting (SED) Solid State Drive with SATA interface |
| Interface | SATA 6 Gb/s |
| Buffer Size | 32 MB |
| Logical Blocks | 976,773,168 |
| Seek Time | 12 ms (Average) |
| Height | 0.267 in/6.8 mm (nominal) |
| Width | 2.75 in/70 mm (nominal) |
| Operating Temperature | 41° to 131° F (5° to 55° C) |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

500 GB 7200RPM 2.5in Self Encrypted Federal Information Processing Standard SATA HDD

| | |
|------------------------------|---|
| Capacity | 500 GB |
| Architecture | Self-Encrypting (SED) Solid State Drive with SATA interface |
| Interface | SATA 6 Gb/s |
| Buffer Size | 32 MB |
| Logical Blocks | 976,773,168 |
| Seek Time | 12 ms (Average) |
| Height | 0.267 in/6.8 mm (nominal) |
| Width | 2.75 in/70 mm (nominal) |
| Operating Temperature | 41° to 131° F (5° to 55° C) |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

500 GB 5400RPM 2.5in SATA SSHD

| | |
|------------------------------|--|
| Capacity | 500 GB |
| Rotational Speed | 5,400 rpm |
| Drive Type | Solid State Hybrid Drive (SSHD) technology with NAND Flash |
| Interface | SATA 6 Gb/s |
| Buffer Size | 64 MB |
| NAND Flash | 8 GB |
| Seek Time | 12 ms (Average) |
| Height | 0.267 in/6.8 mm (nominal) |
| Width | 2.75 in/70 mm (nominal) |
| Operating Temperature | 41° to 131° F (5° to 55° C) |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications

1 TB 5400RPM 2.5in SATA SSHD

| | |
|------------------------------|--|
| Capacity | 1 TB |
| Rotational Speed | 5,400 rpm |
| Drive Type | Solid State Hybrid Drive (SSHD) technology with NAND Flash |
| Interface | SATA 6 Gb/s |
| Buffer Size | 64 MB |
| NAND Flash | 8 GB |
| Seek Time | 12 ms (Average) |
| Height | 0.374 in/9.5 mm (nominal) |
| Width | 2.75 in/70 mm (nominal) |
| Operating Temperature | 41° to 131° F (5° to 55° C) |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2 TB 5400RPM 2.5in SATA SSHD

| | |
|------------------------------|--|
| Capacity | 2 TB |
| Rotational Speed | 5,400 rpm |
| Drive Type | Solid State Hybrid Drive (SSHD) technology with NAND Flash |
| Interface | SATA 6 Gb/s |
| Buffer Size | 128 MB |
| NAND Flash | 8 GB |
| Seek Time | 12 ms (Average) |
| Height | 0.374 in/9.5 mm (nominal) |
| Width | 2.75 in/70 mm (nominal) |
| Operating Temperature | 41° to 131° F (5° to 55° C) |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications

128 GB 2.5in SATA Three Layer Cell SSD

| | |
|---------------------------------|--|
| Drive Weight | <50g |
| Capacity | 128 GB |
| Height | 7mm |
| Length | 100.45mm |
| Width | 69.85mm |
| Interface | SATA 3.0 (6Gb/s) |
| Performance | Up to Random Read/Write = 70K/40K IOPS |
| Maximum Sequential Read | Up to 530MB/s |
| Maximum Sequential Write | Up to 380MB/s |
| Logical Blocks | 250,069,680 |
| Operating Temperature | 0° to 70°C (32° to 158°F) [ambient temp] |
| Features | DIPM; TRIM |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256 GB 2.5in SATA Three Layer Cell SSD

| | |
|---------------------------------|--|
| Drive Weight | <62g |
| Capacity | 256 GB |
| Height | 7mm |
| Length | 100.45mm |
| Width | 69.85mm |
| Interface | SATA 3.0 (6Gb/s) |
| Performance | Up to Random Read/Write = 55K/68K IOPS |
| Maximum Sequential Read | Up to 530MB/s |
| Maximum Sequential Write | Up to 450MB/s |
| Logical Blocks | 500,118,192 |
| Operating Temperature | 0° to 70°C (32° to 158°F) [ambient temp] |
| Features | DIPM; TRIM |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications

512 GB 2.5in SATA Three Layer Cell SSD

| | |
|---------------------------------|--|
| Drive Weight | <50g |
| Capacity | 512 GB |
| Height | 7mm |
| Length | 100.45mm |
| Width | 69.85mm |
| Interface | SATA 3.0 (6Gb/s) |
| Performance | Up to Random Read/Write = 92K/83K IOPS |
| Maximum Sequential Read | Up to 530MB/s |
| Maximum Sequential Write | Up to 500MB/s |
| Logical Blocks | 1,000,215,216 |
| Operating Temperature | 0° to 70°C (32° to 158°F) [ambient temp] |
| Features | DIPM; TRIM |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256 GB 2.5in SATA Self Encrypted OPAL2 Three Layer Cell SSD

| | |
|---------------------------------|--|
| Drive Weight | <50g |
| Capacity | 256 GB |
| Height | 7mm |
| Length | 100.45mm |
| Width | 69.85mm |
| Interface | SATA 3.0 (6Gb/s) |
| Performance | Up to Random Read/Write = 55K/80K IOPS |
| Maximum Sequential Read | Up to 530MB/s |
| Maximum Sequential Write | Up to 500MB/s |
| Logical Blocks | 500,118,192 |
| Operating Temperature | 0° to 70°C (32° to 158°F) [ambient temp] |
| Features | DIPM; TRIM; TCG-OPAL2.0 security |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications

512 GB 2.5in SATA Self Encrypted OPAL2 Three Layer Cell SSD

| | |
|---------------------------------|--|
| Drive Weight | <50g |
| Capacity | 512 GB |
| Height | 7mm |
| Length | 100.45mm |
| Width | 69.85mm |
| Interface | SATA 3.0 (6Gb/s) |
| Performance | Up to Random Read/Write = 92K/83K IOPS |
| Maximum Sequential Read | Up to 530MB/s |
| Maximum Sequential Write | Up to 500MB/s |
| Logical Blocks | 1,000,215,216 |
| Operating Temperature | 0° to 70°C (32° to 158°F) [ambient temp] |
| Features | DIPM; TRIM; TCG-OPAL2.0 security |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256 GB 2.5in SATA Self Encrypted Federal Information Processing Standard SSD

| | |
|---------------------------------|--|
| Drive Weight | <40g |
| Capacity | 256 GB |
| Height | 7mm |
| Length | 100.45mm |
| Width | 69.85mm |
| Interface | SATA 3.0 (6Gb/s) |
| Performance | Up to Random Read/Write = 55K/83K IOPS |
| Maximum Sequential Read | Up to 530MB/s |
| Maximum Sequential Write | Up to 500MB/s |
| Logical Blocks | 500,118,192 |
| Operating Temperature | 0° to 70°C (32° to 158°F) [ambient temp] |
| Features | DIPM; TRIM; FIPS 140-2 security |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications

512 GB 2.5in SATA Self Encrypted Federal Information Processing Standard SSD

| | |
|---------------------------------|--|
| Drive Weight | <45g |
| Capacity | 512 GB |
| Height | 7mm |
| Length | 100.45mm |
| Width | 69.85mm |
| Interface | SATA 3.0 (6Gb/s) |
| Performance | Up to Random Read/Write = 92K/83K IOPS |
| Maximum Sequential Read | Up to 530MB/s |
| Maximum Sequential Write | Up to 500MB/s |
| Logical Blocks | 1,000,215,216 |
| Operating Temperature | 0° to 70°C (32° to 158°F) [ambient temp] |
| Features | DIPM; TRIM; FIPS 140-2 security |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

128 GB M.2 2280 PCIe NVMe SSD

| | |
|---------------------------------|--|
| Drive Weight | < 10g |
| Capacity | 128GB |
| Height | 2.38mm |
| Length | 80mm |
| Width | 22mm |
| Interface | PCIe Gen3 |
| Performance | Up to Random Read/Write = 60K/50K IOPS |
| Maximum Sequential Read | Up to 1400MB/s |
| Maximum Sequential Write | Up to 395MB/s |
| Logical Blocks | 250,069,680 |
| Operating Temperature | 0° to 70°C (32° to 158°F) [ambient temp] |
| Features | APST; ASPM L1.2; NVME spec 1.2 |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications

256 GB M.2 2280 PCIe NVMe SSD

| | |
|---------------------------------|--|
| Drive Weight | < 10g |
| Capacity | 256 GB |
| Height | 2.38mm |
| Length | 80mm |
| Width | 22mm |
| Interface | PCIe Gen3 |
| Performance | Up to Random Read/Write = 120K/170K IOPS |
| Maximum Sequential Read | Up to 1600MB/s |
| Maximum Sequential Write | Up to 780MB/s |
| Logical Blocks | 500,118,192 |
| Operating Temperature | 0° to 70°C (32° to 158°F) [ambient temp] |
| Features | APST; ASPM L1.2; NVME spec 1.2 |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB M.2 2280 PCIe NVMe SSD

| | |
|---------------------------------|--|
| Drive Weight | < 10g |
| Capacity | 512 GB |
| Height | 2.38mm |
| Length | 80mm |
| Width | 22mm |
| Interface | PCIe Gen3 |
| Performance | Up to Random Read/Write = 200K/180K IOPS |
| Maximum Sequential Read | Up to 1600MB/s |
| Maximum Sequential Write | Up to 860MB/s |
| Logical Blocks | 1,000,215,216 |
| Operating Temperature | 0° to 70°C (32° to 158°F) [ambient temp] |
| Features | APST; ASPM L1.2; NVME spec 1.2 |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications

128 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

| | |
|---------------------------------|--|
| Drive Weight | < 10g |
| Capacity | 128 GB |
| Height | 2.38mm |
| Length | 80mm |
| Width | 22mm |
| Interface | PCIe Gen3x4 |
| Performance | Up to Random Read/Write = 140K/40K IOPS |
| Maximum Sequential Read | Up to 2800MB/s |
| Maximum Sequential Write | Up to 600MB/s |
| Logical Blocks | 250,069,680 |
| Operating Temperature | 0° to 70°C (32° to 158°F) [ambient temp] |
| Features | APST; ASPM L1.2; NVME spec 1.2 |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

| | |
|---------------------------------|--|
| Drive Weight | < 10g |
| Capacity | 256GB |
| Height | 2.38mm |
| Length | 80mm |
| Width | 22mm |
| Interface | PCIe Gen3x4 |
| Performance | Up to Random Read/Write = 150K/180K IOPS |
| Maximum Sequential Read | Up to 2700MB/s |
| Maximum Sequential Write | Up to 1000MB/s |
| Logical Blocks | 500,118,192 |
| Operating Temperature | 0° to 70°C (32° to 158°F) [ambient temp] |
| Features | APST; ASPM L1.2; NVME spec 1.2 |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications

512 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

| | |
|---------------------------------|--|
| Drive Weight | < 10g |
| Capacity | 512 GB |
| Height | 2.38mm |
| Length | 80mm |
| Width | 22mm |
| Interface | PCIe Gen3x4 |
| Performance | Up to Random Read/Write = 270K/235K IOPS |
| Maximum Sequential Read | Up to 2900MB/s |
| Maximum Sequential Write | Up to 1100MB/s |
| Logical Blocks | 1,000,215,216 |
| Operating Temperature | 0° to 70°C (32° to 158°F) [ambient temp] |
| Features | APST; ASPM L1.2; NVME spec 1.2 |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1 TB M.2 2280 PCIe NVMe Three Layer Cell SSD

| | |
|---------------------------------|--|
| Drive Weight | < 10g |
| Capacity | 1 TB |
| Height | 2.38mm |
| Length | 80mm |
| Width | 22mm |
| Interface | PCIe Gen3x4 |
| Performance | Up to Random Read/Write = 290K/240K IOPS |
| Maximum Sequential Read | Up to 2900MB/s |
| Maximum Sequential Write | Up to 2100MB/s |
| Logical Blocks | 2,000,409,264 |
| Operating Temperature | 0° to 70°C (32° to 158°F) [ambient temp] |
| Features | APST; ASPM L1.2; NVME spec 1.2 |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications

256 GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

| | |
|---------------------------------|--|
| Drive Weight | < 10g |
| Capacity | 256 GB |
| Height | 2.38mm |
| Length | 80mm |
| Width | 22mm |
| Interface | PCIe Gen3x4 |
| Performance | Up to Random Read/Write = 150K/180K IOPS |
| Maximum Sequential Read | Up to 2700MB/s |
| Maximum Sequential Write | Up to 1000MB/s |
| Logical Blocks | 500,118,192 |
| Operating Temperature | 0° to 70°C (32° to 158°F) [ambient temp] |
| Features | APST; ASPM L1.2; NVME spec 1.2; TCG-OPAL2 security |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

| | |
|---------------------------------|--|
| Drive Weight | < 10g |
| Capacity | 512 GB |
| Height | 2.38mm |
| Length | 80mm |
| Width | 22mm |
| Interface | PCIe Gen3x4 |
| Performance | Up to Random Read/Write = 270K/235K IOPS |
| Maximum Sequential Read | Up to 2900MB/s |
| Maximum Sequential Write | Up to 1100MB/s |
| Logical Blocks | 1,000,215,216 |
| Operating Temperature | 0° to 70°C (32° to 158°F) [ambient temp] |
| Features | APST; ASPM L1.2; NVME spec 1.2; TCG-OPAL2 security |

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Technical Specifications

HP 9.5mm Slim DVD-ROM Drive

| | |
|--|--|
| Height | 9.5 mm height |
| Orientation | Either horizontal or vertical |
| Interface type | SATA/ATAPI |
| Dimensions (W x H x D) | 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel |
| Weight (max) | Up to 0.31 lb (140g) without bezel |
| Read Speeds | DVD+R/-R/+RW/ -RW/+R DL /-R DL Up to 8X DVD-ROM Up to 8X CD-ROM, CD-R Up to 24X CD-RW Up to 24X |
| Access time (typical reads, including settling) | Random: DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full stroke: DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) |
| Power | Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC \pm 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum) |
| Environmental conditions (operating - non-condensing) | Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C) |

HP 9.5mm Slim DVD Writer Drive

| | |
|--|---|
| Height | 9.5 mm height |
| Orientation | Either horizontal or vertical |
| Interface type | SATA/ATAPI |
| Disc recording capacity | Up to 8.5 GB DL or 4.7 GB standard |
| Dimensions (W x H x D) | 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel |
| Weight (max) | 0.31 lb (140 g) |
| Read Speeds | DVD-R DL - Up to 6X DVD+R - Up to 8X DVD+RW - Up to 8X DVD+R DL - Up to 6X DVD-R - Up to 8X DVD-RW - Up to 6X CD-R - Up to 24X CD-RW - Up to 10X DVD-RW, DVD+RW - Up to 8X DVD-R DL, DVD+R DL - Up to 8X DVD+R, DVD-R - Up to 8X DVD-ROM DL, DVD-ROM - Up to 8X CD-ROM, CD-R - Up to 24X CD-RW - Up to 24X |
| Access time (typical reads, including settling) | Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical) |
| Power | Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC \pm 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum) |
| Environmental conditions (operating - non-condensing) | Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% |

Technical Specifications

Maximum Wet Bulb Temperature 84° F (29° C)

HP 9.5mm Slim Blu-Ray Writer Drive

| | |
|--|---|
| Height | 9.5 mm height |
| Orientation | Either horizontal or vertical |
| Interface type | SATA/ATAPI |
| Disc recording capacity | Up to 128 GB QL, 100 GB TL, 50 GB DL or 25 GB standard SL |
| Dimensions (W x H x D) | 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel |
| Weight (max) | 0.29 lb (132 g) |
| | BD-R Up to 4X |
| | BD-RE Up to 2X |
| | BD-R Up to 6X |
| | BD-RE Up to 2X |
| | DVD-R Up to 8X |
| | DVD-RW Up to 6X |
| | DVD+R Up to 8X |
| | DVD+RW Up to 8X |
| | DVD-RAM Up to 5X |
| | CD-R Up to 24X |
| Write Speeds | CD-RW Up to 10X |
| Read Speeds | BD-R Up to 6X |
| | BD-RE Up to 4X |
| | BD-ROM Up to 6X |
| | BD-R Up to 6X |
| | BD-RE Up to 6X |
| | DVD-ROM Up to 8X |
| | DVD-R Up to 8X |
| | DVD-RW Up to 8X |
| | DVD+R Up to 8X |
| | DVD+RW Up to 8X |
| | BDMV (AACs Compliant Disc) |
| | Up to 6x/2x (Read/Play) |
| | DVD-RAM Up to 5x |
| | DVD-Video (CSS Compliant Disc) |
| | Up to 8x/4x (Read/Play) |
| | CD-R/RW/ROM Up to 24x |
| | CD-DA (DAE) Up to 24X/10X (Read/Play) |
| Access time (typical reads, including settling) | Random BD-ROM: 205 ms (typical), DVD-ROM: 185 ms (typical), CD-ROM: 165 ms (typical) |
| | Full Stroke BD-ROM: 350 ms (typical), DVD-ROM: 345 ms (typical), CD-ROM: 340 ms (typical) |
| Power | Source Slimline SATA DC power receptacle |
| | DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p |
| | DC Current 5 VDC -1200 mA typical, 2000 mA maximum |
| Environmental conditions (operating - non-condensing) | Temperature 41° to 122° F (5° to 50° C) |
| | Relative Humidity 10% to 80% |
| | Maximum Wet Bulb Temperature 84° F (29° C) |

Technical Specifications

NETWORKING AND COMMUNICATIONS

| Intel® i219LM 10/100/1000 Integrated NIC | |
|---|---|
| Connector | RJ-45 |
| System Interface | PCI (Intel proprietary) + SMBus |
| Data rates supported | 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s |
| IEEE Compliance | IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet) |
| Performance | TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K |
| Power consumption | Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW |
| Power Management | ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption |
| Management Interface | Auto MDI/MDIX Crossover cable detection |
| IT Manageability | Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status |

Technical Specifications

| | |
|---|---|
| Security & Manageability | Intel® vPro™ support with appropriate Intel® chipset components |
| Intel® i210 10/100/1000 Add-on NIC | |
| Connector | RJ-45 |
| System Interface | PCI (Intel proprietary) + SMBus |
| Data rates supported | 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s |
| IEEE Compliance | IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet) |
| Performance | TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K |
| Power consumption | Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW |
| Power Management | ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption |
| Management Interface | Auto MDI/MDIX Crossover cable detection |
| IT Manageability | Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status |

Technical Specifications

| | |
|--|--|
| Security & Manageability | Intel® vPro™ support with appropriate Intel® chipset components |
| Intel® 9560 802.11AC 2x2 with Bluetooth® M.2 Combo Card vPro™ | |
| Wireless LAN Standards | IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac |
| Interoperability | Wi-Fi certified |
| Frequency Band | 802.11b/g/n <ul style="list-style-type: none"> • 2.402 – 2.482 GHz 802.11a/n <ul style="list-style-type: none"> • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz |
| Data Rates | <ul style="list-style-type: none"> • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) |
| Modulation | Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM |
| Security¹ | <ul style="list-style-type: none"> • IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • Cisco Certified Extensions, all versions through CCX4 and CCX Lite • WAPI |
| Network Architecture Models | Ad-hoc (Peer to Peer) Infrastructure (Access Point Required) |
| Roaming | IEEE 802.11 compliant roaming between access points |
| Output Power² | <ul style="list-style-type: none"> • 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum |
| Power Consumption | <ul style="list-style-type: none"> • Transmit mode 2.0 W • Receive mode 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode 50 mW (WLAN unassociated) • Connected Standby 10mW • Radio disabled 8 mW |
| Power Management | ACPI and PCI Express compliant power management 802.11 compliant power saving mode |
| Receiver Sensitivity³ | 802.11b, 1Mbps : -93.5dBm maximum 802.11b, 11Mbps : -84dBm maximum |

Technical Specifications

| | | |
|---|---|---|
| | 802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum 802.11ac, MCS0 : -84dBm maximum 802.11ac, MCS9 : -59dBm maximum | |
| Antenna type | High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications | |
| Form Factor | PCI-Express M.2 MiniCard | |
| Dimensions | Type 2230: 2.3 x 22.0 x 30.0 mm | |
| Weight | Type 2230: 2.8g | |
| Operating Voltage | 3.3v +/- 9% | |
| Temperature | Operating Non-operating | 14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C) |
| Humidity | Operating Non-operating | 10% to 90% (non-condensing) 5% to 95% (non-condensing) |
| Altitude | Operating Non-operating | 0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m) |
| LED Activity | LED Amber – Radio OFF; LED White – Radio ON | |
| 1. Check latest software/driver release for updates on supported security features. 2. Maximum output power may vary by country according to local regulations. 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation). | | |
| HP Integrated Module with Bluetooth® 4.0/4.1/4.2/5.0 Wireless Technology | | |
| Bluetooth® Specification | 4.0/4.1/4.2/5.0 Compliant | |
| Frequency Band | 2402 to 2480 MHz | |
| Number of Available Channels | Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH) | |
| Data Rates and Throughput | Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels | |
| Transmit Power | The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR. | |
| Power Consumption | Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW | |
| Range | Legacy Up to 33 ft (10 m) BLE Up to 99 ft (30 m) | |
| Bluetooth® Software Supported Link Topology | Microsoft Windows Bluetooth® Software | |
| Power Management | Microsoft Windows ACPI, and USB Bus Support | |
| Certifications | FCC (47 CFR) Part 15C, Section 15.247 & 15.249 ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark | |
| Bluetooth Profiles Supported | BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels | |

Technical Specifications

| | |
|-------------------------------------|--|
| | Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) |
| Security & Manageability | Intel® vPro™ support with appropriate Intel® chipset components |

| Intel® 9560 802.11AC 2x2 with Bluetooth® M.2 Combo Card non-vPro™ | |
|--|---|
| Wireless LAN Standards | IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac |
| Interoperability | Wi-Fi certified |
| Frequency Band | 802.11b/g/n • 2.402 – 2.482 GHz 802.11a/n • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz |
| Data Rates | • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) |
| Modulation | Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM |
| Security¹ | • IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • Cisco Certified Extensions, all versions through CCX4 and CCX Lite • WAPI |
| Network Architecture Models | Ad-hoc (Peer to Peer) Infrastructure (Access Point Required) |
| Roaming | IEEE 802.11 compliant roaming between access points |
| Output Power² | • 802.11b : +18.5dBm minimum • 802.11g : +17.5dBm minimum • 802.11a : +18.5dBm minimum • 802.11n HT20(2.4GHz) : +15.5dBm minimum • 802.11n HT40(2.4GHz) : +14.5dBm minimum • 802.11n HT20(5GHz) : +15.5dBm minimum • 802.11n HT40(5GHz) : +14.5dBm minimum • 802.11ac VHT80(5GHz) : +11.5dBm minimum • 802.11ac VHT160(5GHz) : +11.5dBm minimum |

Technical Specifications

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|--|--|--------------------------------|
| Power Consumption | <ul style="list-style-type: none">• Transmit mode 2.0 W• Receive mode 1.6 W• Idle mode (PSP) 180 mW (WLAN Associated)• Idle mode 50 mW (WLAN unassociated)• Connected Standby 10mW• Radio disabled 8 mW | |
| Power Management | ACPI and PCI Express compliant power management 802.11 compliant power saving mode | |
| Receiver Sensitivity³ | 802.11b, 1Mbps : -93.5dBm maximum 802.11b, 11Mbps : -84dBm maximum 802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum 802.11ac, MCS0 : -84dBm maximum 802.11ac, MCS9 : -59dBm maximum | |
| Antenna type | High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications | |
| Form Factor | PCI-Express M.2 MiniCard | |
| Dimensions | Type 2230: 2.3 x 22.0 x 30.0 mm | |
| Weight | Type 2230: 2.8g | |
| Operating Voltage | 3.3v +/- 9% | |
| Temperature | Operating | 14° to 158° F (–10° to 70° C) |
| | Non-operating | –40° to 176° F (–40° to 80° C) |
| Humidity | Operating | 10% to 90% (non-condensing) |
| | Non-operating | 5% to 95% (non-condensing) |
| Altitude | Operating | 0 to 10,000 ft (3,048 m) |
| | Non-operating | 0 to 50,000 ft (15,240 m) |
| LED Activity | LED Amber – Radio OFF; LED White – Radio ON | |
| <div>1. Check latest software/driver release for updates on supported security features.</div> <div>2. Maximum output power may vary by country according to local regulations.</div> <div>3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).</div> | | |
| HP Integrated Module with Bluetooth® 4.0/4.1/4.2/5.0 Wireless Technology | | |
| Bluetooth® Specification | 4.0/4.1/4.2/5.0 Compliant | |
| Frequency Band | 2402 to 2480 MHz | |
| Number of Available Channels | Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH) | |
| Data Rates and Throughput | Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels | |
| Transmit Power | The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR. | |
| Power Consumption | Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW | |
| Range | Legacy Up to 33 ft (10 m) BLE Up to 99 ft (30 m) | |
| Bluetooth® Software Supported Link Topology | Microsoft Windows Bluetooth® Software | |
| Power Management | Microsoft Windows ACPI, and USB Bus Support | |

Technical Specifications

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|-------------------------------------|--|
| Certifications | FCC (47 CFR) Part 15C, Section 15.247 & 15.249 ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark |
| Bluetooth Profiles Supported | BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) |

| Realtek RTL8822BE 802.11ac 2x2 with Bluetooth® M.2 Combo Card | |
|--|---|
| Wireless LAN Standards | IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac |
| Interoperability | Wi-Fi certified |
| Frequency Band | 802.11b/g/n • 2.402 – 2.482 GHz 802.11a/n • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz |
| Data Rates | • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) |
| Modulation | Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM |
| Security¹ | • IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • Cisco Certified Extensions, all versions through CCX4 and CCX Lite • WAPI |
| Network Architecture Models | Ad-hoc (Peer to Peer) Infrastructure (Access Point Required) |
| Roaming | IEEE 802.11 compliant roaming between access points |



Technical Specifications

| | | |
|--|--|---|
| Output Power² | <ul style="list-style-type: none">• 802.11b: +14dBm minimum• 802.11g: +12dBm minimum• 802.11a: +12dBm minimum• 802.11n HT20(2.4GHz): +12dBm minimum• 802.11n HT40(2.4GHz): +12dBm minimum• 802.11n HT20(5GHz): +10dBm minimum• 802.11n HT40(5GHz): +10dBm minimum• 802.11ac VHT80(5GHz): +10dBm minimum | |
| Power Consumption | <ul style="list-style-type: none">• Transmit mode2.0 W• Receive mode 1.6 W• Idle mode (PSP) 180 mW (WLAN Associated)• Idle mode 50 mW (WLAN unassociated)• Connected Standby 10mW• Radio disabled 8 mW | |
| Power Management | ACPI and PCI Express compliant power management 802.11 compliant power saving mode | |
| Receiver Sensitivity³ | 802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum | |
| Antenna type | High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications | |
| Form Factor | PCI-Express M.2 MiniCard | |
| Dimensions | Type 2230 : 2.3 x 22.0 x 30.0 mm | |
| Weight | Type 2230 : 2.8g | |
| Operating Voltage | 3.3v +/- 9% | |
| Temperature | Operating Non-operating | 14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C) |
| Humidity | Operating Non-operating | 10% to 90% (non-condensing) 5% to 95% (non-condensing) |
| Altitude | Operating Non-operating | 0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m) |
| LED Activity | LED Amber – Radio OFF; LED White – Radio ON | |
| <div>1. Check latest software/driver release for updates on supported security features.</div> <div>2. Maximum output power may vary by country according to local regulations.</div> <div>3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).</div> | | |
| HP Integrated Module with Bluetooth® 4.0/4.1/4.2 Wireless Technology | | |
| Bluetooth® Specification | 4.0/4.1/4.2 Compliant | |
| Frequency Band | 2402 to 2480 MHz | |
| Number of Available Channels | Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH) | |
| Data Rates and Throughput | Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5) | |

Technical Specifications

| | |
|--|--|
| Transmit Power | The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR. |
| Power Consumption | Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW |
| Electrical Interface | USB 2.0 compliant |
| Bluetooth® Software Supported Link Topology | Microsoft Windows Bluetooth® Software |
| Power Management | Microsoft Windows ACPI, and USB Bus Support |
| Certifications | FCC (47 CFR) Part 15C, Section 15.247 & 15.249 ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark |
| Bluetooth Profiles Supported | BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) |

| Realtek RTL8821CE 802.11ac 1x1 with Bluetooth® M.2 Combo Card | |
|--|--|
| Wireless LAN Standards | IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac |
| Interoperability | Wi-Fi certified |
| Frequency Band | 802.11b/g/n • 2.402 – 2.482 GHz 802.11a/n • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz |
| Data Rates | • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz) |
| Modulation | Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM |

Technical Specifications

| | | |
|--|--|---|
| Security¹ | <ul style="list-style-type: none">• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only• AES-CCMP: 128 bit in hardware• 802.1x authentication• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.• WPA2 certification• IEEE 802.11i• Cisco Certified Extensions, all versions through CCX4 and CCX Lite• WAPI | |
| Network Architecture Models | Ad-hoc (Peer to Peer) Infrastructure (Access Point Required) | |
| Roaming | IEEE 802.11 compliant roaming between access points | |
| Output Power² | <ul style="list-style-type: none">• 802.11b : +14dBm minimum• 802.11g : +12dBm minimum• 802.11a : +12dBm minimum• 802.11n HT20(2.4GHz) : +12dBm minimum• 802.11n HT40(2.4GHz) : +12dBm minimum• 802.11n HT20(5GHz) : +10dBm minimum• 802.11n HT40(5GHz) : +10dBm minimum• 802.11ac VHT80(5GHz) : +10dBm minimum | |
| Power Consumption | <ul style="list-style-type: none">• Transmit mode 2.0 W• Receive mode 1.6 W• Idle mode (PSP) 180 mW (WLAN Associated)• Idle mode 50 mW (WLAN unassociated)• Connected Standby 10mW• Radio disabled 8 mW | |
| Power Management | ACPI and PCI Express compliant power management 802.11 compliant power saving mode | |
| Receiver Sensitivity³ | 802.11b, 1Mbps : -93.5dBm maximum 802.11b, 11Mbps : -84dBm maximum 802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum 802.11ac, MCS0 : -84dBm maximum 802.11ac, MCS9 : -59dBm maximum | |
| Antenna type | High efficiency antenna. One embedded dual band 2.4/5 GHz antenna is provided to the card to support WLAN communications and Bluetooth communications | |
| Form Factor | PCI-Express M.2 MiniCard | |
| Dimensions | Type 2230 : 2.3 x 22.0 x 30.0 mm | |
| Weight | Type 2230 : 2.8g | |
| Operating Voltage | 3.3v +/- 9% | |
| Temperature | Operating Non-operating | 14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C) |
| Humidity | Operating Non-operating | 10% to 90% (non-condensing) 5% to 95% (non-condensing) |
| Altitude | Operating Non-operating | 0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m) |
| LED Activity | LED Amber – Radio OFF; LED White – Radio ON | |
| <div>1. Check latest software/driver release for updates on supported security features.</div> <div>2. Maximum output power may vary by country according to local regulations.</div> <div>3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).</div> | | |
| HP Integrated Module with Bluetooth® 4.0/4.1/4.2 Wireless Technology | | |
| Bluetooth® Specification | 4.0/4.1/4.2 Compliant | |

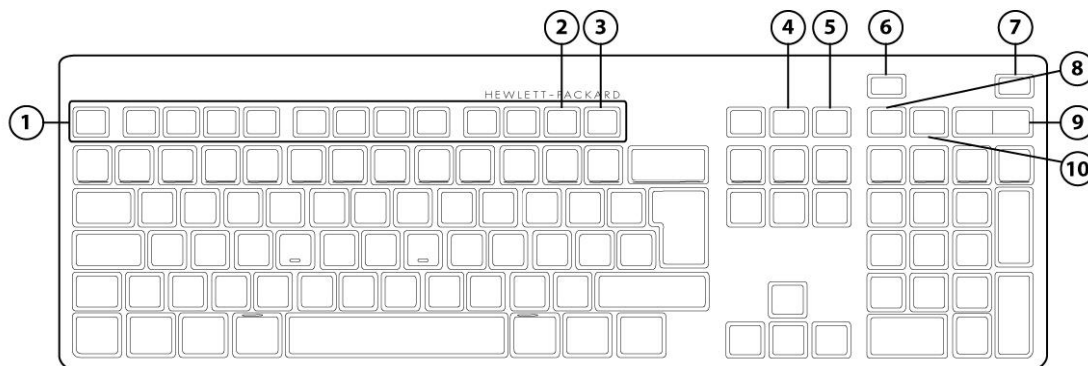
Technical Specifications

| | |
|--|--|
| Frequency Band | 2402 to 2480 MHz |
| Number of Available Channels | Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH) |
| Data Rates and Throughput | Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5) |
| Transmit Power | The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR. |
| Power Consumption | Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW |
| Electrical Interface | USB 2.0 compliant |
| Bluetooth® Software Supported Link Topology | Microsoft Windows Bluetooth® Software |
| Power Management | Microsoft Windows ACPI, and USB Bus Support |
| Certifications | ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark |
| Bluetooth Profiles Supported | BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) |

Technical Specifications

I/O DEVICES

HP Conferencing Keyboard



- | | | | |
|----|--|-----|--------------------|
| 1. | Function Keys | 6. | End/Decline a Call |
| 2. | F11 Lync or Skype for Business Contact list[1] | 7. | Answer a Call |
| 3. | F12 Lync or Skype for Business Calendar[2] | 8. | Microphone Mute |
| 4. | Share Screen | 9. | Volume Up/Down |
| 5. | Stop Webcam | 10. | Audio Mute |

1. Microsoft Lync 2013, or Skype for Business, or Microsoft Outlook 2013 Contact list

2. Microsoft Lync 2013, or Skype for Business, or Microsoft Outlook 2013 Calendar

HP USB Premium Keyboard

| | | |
|---------------------------------|-------------------------|--|
| Physical Characteristics | Keys | 104, 105 layout (depending upon country) |
| | Dimensions (L x W x H) | 17.04 x 5.55 x 0.52 in (433 x 141 x 13.2 mm) |
| | Weight | 1.54 lb. (698g) |
| Electrical | Operating voltage | 5 VDC, +/-5% |
| | Power consumption | 35mA (All LED on) |
| | System interface | USB Type A plug connector |
| | ESD | Contact Discharge: 8 KV Air Discharge: 15 KV |
| | EMI - RFI | Conforms to FCC rules for a Class B computing device |
| | Microsoft® PC 99 - 2001 | Functionally compliant |
| Mechanical | Keycaps | Low-profile design |
| | Switch actuation | 60±10g nominal peak force with tactile feedback |
| | Switch life | 10 million keystrokes (Life tester) |
| | Switch type | Contamination-resistant switch membrane |
| | Key-leveling mechanisms | For all double-wide and greater-length keys |
| | Cable length | 6 ft. (1.8 m) |
| | Microsoft PC 99 - 2001 | Mechanically compliant |

Technical Specifications

| | | |
|-----------------------------|--|---|
| Environmental | Acoustics | 43-dBA maximum sound pressure level |
| | Operating temperature | 50° to 122° F (10° to 50° C) |
| | Non-operating temperature | -22° to 140° F (-30° to 60° C) |
| | Operating humidity | 10% to 90% (non-condensing at ambient) |
| | Non-operating humidity | 20% to 80% (non-condensing at ambient) |
| | Operating shock | 40 g, six surfaces |
| | Non-operating shock | 80 g, six surfaces |
| | Operating vibration | 2-g peak acceleration |
| | Non-operating vibration | 4-g peak acceleration |
| | Drop (out of box) | 26 in (66 cm) on carpet, six-drop sequence |
| | Drop (in box) | 30 in (76.2 cm) on concrete, 16-drop sequence |
| Approvals | UL, FCC, CE Mark, TUV GS, VCCI, BSMI, C-Tick, KC | |
| Ergonomic compliance | TUVGS | |
| Kit contents | Keyboard, QSP | |
| Warranty Card | Product Notice | |

| Skylab USB Wired Keyboard | | |
|----------------------------------|-------------------------|---|
| Physical Characteristics | Keys | 104, 105, 106, 107, 109 layout (depending upon country) |
| | Dimensions (L x W x H) | 171.97 x 68.35 x 8.27 in (436.8± 1.5 x 137.6± 1.0 x 21.0± 1.0 cm) |
| | Weight | 1.32 lb. (0.6± 0.08 kg) |
| Electrical | Operating voltage | 4.4-5.25VDC |
| | Power consumption | 50-mA maximum (with 5 VDC power supplied and three LEDs ON) |
| | System interface | USB |
| | ESD | Contact Discharge: 2, 4, 6, 8KV Air Discharge: 2, 4, 8, 10, 12.5KV |
| | EMI - RFI | Conforms to FCC rules for a Class B computing device |
| Mechanical | Keycaps | Low-profile design |
| | Switch actuation | 60±10g nominal peak force with tactile feedback |
| | Switch life | 10 million keystrokes (Life tester) |
| | Switch type | Contamination-resistant switch membrane |
| | Key-leveling mechanisms | For all double-wide and greater-length keys |
| | Cable length | 6 ft. (1.8 m) |
| | Microsoft PC 99 - 2001 | Mechanically compliant |
| Environmental | Acoustics | 43-dBA maximum sound pressure level |

Technical Specifications

| | | |
|-----------------------------|---|---|
| | Operating temperature | 50° to 122° F (10° to 50° C) |
| | Non-operating temperature | Minus 30 degrees to 60 degrees Celsius |
| | Operating humidity | 10% to 90% (non-condensing at ambient) |
| | Non-operating humidity | 20% to 80% (non-condensing at ambient) |
| | Operating shock | 40 g, six surfaces |
| | Non-operating shock | 80 g, six surfaces |
| | Operating vibration | 2-g peak acceleration |
| | Non-operating vibration | 4-g peak acceleration |
| | Drop (out of box) | 26 in (66 cm) on carpet, six-drop sequence |
| | Drop (in box) | 30 in (76.2 cm) on concrete, 16-drop sequence |
| Approvals | UL, FCC, CE Mark, TUV GS, VCCI, BSMI, C-Tick, KC | |
| Ergonomic compliance | ANSI HFS 100, ISO 9241-4, and TUVGS | |
| Kit contents | Keyboard, Installation Guide, Warranty card, Safety and Comfort Guide | |

Technical Specifications

| HP USB Premium Mouse | | |
|-------------------------------|--|--|
| Dimensions (H x L x W) | 4.21 x 2.64 x 1.52 in (107 x 67 x 38.7 mm) | |
| Weight | 0.19lb (90g) | |
| Environmental | Operating temperature | 50° to 122°F (10° to 50° C) |
| | Non-operating temperature | -22° to 140°F (-30° to 60° C) |
| | Operating humidity | 10% to 90% (non-condensing at ambient) |
| | Non-operating humidity | 20% to 80% (non-condensing at ambient) |
| | Operating shock | 50 g, 6 surfaces |
| | Non-operating shock | 80 g, 6 surfaces |
| | Operating vibration | 2 g peak acceleration |
| | Non-operating vibration | 4 g peak acceleration |
| Electrical | Operating voltage | 5 VDC, +/-5% |
| | Power consumption | 12mA |
| Mechanical | Connector | USB 2.0 |
| | Type | 3D mouse (3 keys and wheel) |
| | Resolution | 800, 1200, 1600 DPI |
| | Sensor | Pixart PAN3606DL |
| Tracking speed | Tracking acceleration | 8G(max), 1G=9.8m/s ² |
| | Cable length | 6 ft. (1.8 m) |
| | Color | Jack Black |
| Regulatory approvals | Compliant | UL, FCC, CE Mark, TUV GS, VCCI, BSMI, C-Tick, KC |

| HP USB Mouse | | |
|----------------------------------|-------------------|--|
| Dimensions (H x L x W) | 37mm*115mm*62.9mm | |
| Weight | 90 +10g/- 5 g | |
| Color | Black | |
| Connector | USB | |
| Mechanical | Resolution | 800 DPI sensitivity |
| | Buttons | Two primary buttons and clickable scroll wheel |

Technical Specifications

AUDIO/MULTIMEDIA

HP EliteDesk 800 G4 Tower Business PC

| | |
|----------------------------|--|
| Type | Integrated |
| HD Stereo Codec | Conexant CX20632 |
| | Front: 1 - Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-out, Microphone-in or Headphone-out port 1 - Headphone port Rear: Line-out Line-in which is retaskable as a Microphone Input All ports are 3.5mm and support stereo |
| Audio I/O Ports | |
| Internal Speaker Amplifier | 2W class D mono amplifier for the internal speaker only. External speakers must be powered |
| Multi-streaming Capable | Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speaker. |
| Sampling | Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC |
| Wavetable Syntheses | Yes - Uses OS soft wavetable |
| Analog Audio | Yes |
| # of Channels on Line-Out | Stereo (Left & Right channels) |
| Internal Speaker | Yes |

HP EliteDesk 800 G4 Small Form Factor Business PC

| | |
|----------------------------|--|
| Type | Integrated |
| HD Stereo Codec | Conexant CX20632 |
| | Front: 1 - Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-out, Microphone-in or Headphone-out port 1 - Headphone port Rear: Line-out Line-in which is retaskable as a Microphone Input All ports are 3.5mm and support stereo |
| Audio I/O Ports | All ports are 3.5mm and support stereo |
| Internal Speaker Amplifier | 2W class D mono amplifier for the internal speaker only. External speakers must be powered |
| Multi-streaming Capable | Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speaker. |
| Sampling | Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC |
| Wavetable Syntheses | Yes - Uses OS soft wavetable |
| Analog Audio | Yes |
| # of Channels on Line-Out | Stereo (Left & Right channels) |
| Internal Speaker | Yes |

Technical Specifications

HP EliteDesk 800 G4 Desktop Mini Business PC

| | |
|----------------------------|--|
| Type | Integrated |
| HD Stereo Codec | Conexant CX20632 |
| Audio I/O Ports | Front: 1 - Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-out, Microphone-in or Headphone-out port 1 - Headphone port |
| Internal Speaker Amplifier | 2W class D mono amplifier for the internal speaker only. External speakers must be powered |
| Multi-streaming Capable | Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speaker. |
| Sampling | Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC |
| Wavetable Syntheses | Yes - Uses OS soft wavetable |
| Analog Audio | Yes |
| # of Channels on Line-Out | Stereo (Left & Right channels) |
| Internal Speaker | Yes |

HP EliteOne 800 G4 All-in-One Business PC

Bang & Olufsen Audio

| | |
|----------------------------|---|
| Type | Integrated |
| HD Stereo Codec | Conexant CX5001 |
| Audio I/O Ports | Side headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-out, Microphone-in or Headphone-out port Side headphone connector supports a headphone connections Rear line out connector |
| Internal Speaker Amplifier | All ports are 3.5mm and support stereo 2W per channel class D stereo amplifier for the internal speakers only |
| Multi-streaming Capable | Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speakers. |
| Sampling | Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC |
| Wavetable Syntheses | Yes - Uses OS soft wavetable |
| Analog Audio | Yes |
| # of Channels on Line-Out | Stereo (Left & Right channels) |
| Internal Speaker | Yes - Stereo |

Technical Specifications

INTEGRATED WEBCAM AND MICROPHONE

Integrated Webcam and Microphone

Optional integrated 2 MP Full HD RGB webcam & microphone; maximum resolution of 1920 x 1080

Optional integrated 2 MP Full HD RGB dual-facing webcam with IR sensor (user-facing) & microphone; maximum resolution of 1920 x 1080

NOTE: All HP devices which carry the Bang & Olufsen brand are custom-tuned with Bang & Olufsen's acoustical engineers for precise sound experience in business use.

POWER**HP EliteDesk 800 G4 Tower Business PC****Unit Environment and Operating Conditions**

| | |
|-------------------------------------|--|
| Temperature Range | Operating: 5°C ~45°C |
| | Non-Operating: -40°C ~66°C |
| Relative Humidity | Operating 5% to 90% relative humidity at max inlet temperature |
| | Non-Operating 5% to 90% relative humidity at max inlet temperature |
| Maximum Altitude (unpressurized) | Operating: 5000m |
| | Non-operating: 50,000 ft. (15240 m) |

HP EliteDesk 800 G4 Desktop Mini Business PC (35W)**Unit Environment and Operating Conditions**

| | |
|-------------------------------------|--|
| Temperature Range | Operating: 5°C ~35°C |
| | Non-Operating: -40°C ~66°C |
| Relative Humidity | Operating 5% to 90% relative humidity at max inlet temperature |
| | Non-Operating 5% to 90% relative humidity at max inlet temperature |
| Maximum Altitude (unpressurized) | Operating: 5000m |
| | Non-operating: 50,000 ft. (15240 m) |

HP EliteDesk 800 G4 Desktop Mini Business PC (65W)**Unit Environment and Operating Conditions**

| | |
|-------------------------------------|--|
| Temperature Range | Operating: 5°C ~35°C |
| | Non-Operating: -40°C ~66°C |
| Relative Humidity | Operating 5% to 90% relative humidity at max inlet temperature |
| | Non-Operating 5% to 90% relative humidity at max inlet temperature |
| Maximum Altitude (unpressurized) | Operating: 5000m |
| | Non-operating: 50,000 ft. (15240 m) |

HP EliteDesk 800 G4 Desktop Mini Business PC (95W)**Unit Environment and Operating Conditions**

| | |
|-------------------------------------|--|
| Temperature Range | Operating: 5°C ~35°C |
| | Non-Operating: -40°C ~66°C |
| Relative Humidity | Operating 5% to 90% relative humidity at max inlet temperature |
| | Non-Operating 5% to 90% relative humidity at max inlet temperature |
| Maximum Altitude (unpressurized) | Operating: 5000m |
| | Non-operating: 50,000 ft. (15240 m) |

Technical Specifications

HP EliteOne 800 G4 All-in-One Business PC

Unit Environment and Operating Conditions

| | |
|-------------------------------------|--|
| Temperature Range | Operating: 5°C ~45°C Non-Operating: -40°C ~66°C |
| Relative Humidity | Operating 5% to 90% relative humidity at max inlet temperature Non-Operating 5% to 90% relative humidity at max inlet temperature |
| Maximum Altitude (unpressurized) | Operating: 5000m Non-operating: 50,000 ft. (15240 m) |

| | DM | SFF | TWR | AiO |
|--|---|--|--|---|
| External Power Supplies | 65W EPS, 89% average efficiency at 115V & 230Vac 90W EPS, 89% average efficiency at 115V & 230Vac 150W EPS, 89% average efficiency at 115V & 230Vac | N/A | N/A | N/A |
| 80 PLUS Gold | N/A | N/A | 500W active PFC / 80 PLUS Gold 87/90/87% efficient at 20/50/100% load (115V) | 180W active PFC / 80 PLUS Gold* 87/90/87% efficient at 20/50/100% load (115V) <small>*Available on models with integrated graphics</small> |
| 80 PLUS Platinum | N/A | 250W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V) | 250W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V) | 210W active PFC / 80 PLUS Platinum* 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V) <small>*Available on models with discrete graphics</small> |
| Operating Voltage Range | 90Vac~264Vac | 90Vac~264Vac | 90Vac~264Vac | 90Vac~264Vac |
| Rated Voltage Range | 100Vac~240Vac | 100Vac~240Vac | 100Vac~240Vac | 100Vac~240Vac |
| Rated Line Frequency | 50HZ~60HZ | 50HZ~60HZ | 50HZ~60HZ | 50HZ~60HZ |
| Operating Line Frequency | 47HZ~63HZ | 47HZ~63HZ | 47HZ~63HZ | 47HZ~63HZ |
| Rated Input Current | 65W≤1.6A 90W≤1.2A 150W≤2.2A | 250W≤3A | 500W≤6A 250W≤3A | 210W≤3A 180W≤2.5A |
| Rated Input Current with Energy Efficient* Power Supply | 65W≤1.6A 90W≤1.2A 150W≤2.2A | 250W≤3A | 500W≤6A 250W≤3A | 210W≤3A 180W≤2.5A |
| DC Output | +19.5VV | +12V | +12V | +12V |

Technical Specifications

| | DM | SFF | TWR | AiO |
|--|---|---|---|---|
| Current Leakage (NFPA 99: 2102) | Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. | Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. | Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. | Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. |
| Power Supply Fan | N/A | 70mm variable speed | 70mm variable speed | N/A |
| Power cord length | 6.0 ft. (1.83 m) | 6.0 ft. (1.83 m) | 6.0 ft. (1.83 m) | 6.0 ft. (1.83 m) |
| External Power Adapter | External power supply | Internal power supply | Internal power supply | Internal power supply |
| Dimensions | 65W: 113.5mm x 55mm x 30mm 90W: 132mm x 57mm x 30mm 150W: 160mm x 80mm x 40mm | 165mm x 95mm x 73mm | 165mm x 95mm x 73mm | 135mm x 100mm x 19.52mm |
| Total Cord Length | 6.0 ft. (1.83 m) | 6.0 ft. (1.83 m) | 6.0 ft. (1.83 m) | 6.0 ft. (1.83 m) |

Technical Specifications

WEIGHTS & DIMENSIONS

| | DM | SFF | TWR | AiO |
|---|---|--|--|--|
| Chassis (W x D x H) | 177x175x34mm | 3.94 x 13.3 x 12.13 in 100 x 338 x 308 mm | 6.1 x 14.6 x 14.4 in 154 x 370 x 365 mm | See table below. |
| System Volume | 1.05L | 10.4 L 634 cu in | 20.8 L 1269 cu in | See table below. |
| System Weight | 1.05 kg 2.31 lb | 6.13 kg 13.5 lb | 9.86 kg 21.74 lb | See table below. |
| Max Supported Weight (desktop orientation) | 0 | 35 kg 77 lb | 35 kg 77 lb | See table below. |
| Stand Dimensions | 160x117x18.5mm | 151.8x200x37.2mm | N/A | See table below. |
| Packaging (W x D x H) | 497 x128 x223mm | 15.71 x 19.65 x 9.06 in 399 x 499 x 230 mm | 11.77 x 18.82 x 20.35 in 299 x 478 x 517 mm | See table below. |
| Shipping Weight | 2.95 kg 6.49 lb | 9 kg 19.82 lb | 11.34 kg 24.98 lb | See table below. |
| Multipack Packaging (10 units) | 20.28x16.54x25 in 515x420x636 mm | | | |
| Palletization Profile | 18-units per layer 5 or 6 layers max depending on details of air freight 90 or 108 units per pallet depending on details of air freight 45.354 x 39.13 x 57.80 in, 1152 x 994 x 1468 mm (include pallet) | 6 units per layer 10 layers max 60 units per pallet 1200*1000*2438 mm (include the pallet) | 8 units per layer 4 layers ax 32 units per pallet 1200*1000*2203 mm (include the pallet) | 10-units per layer 4-layers max 40-units per pallet (sea) 1200 x 1000 x 2470 mm |

Technical Specifications

ALL-IN-ONE WEIGHTS AND DIMENSIONS

Weight with Touch Panel

| | | | |
|-------------------------------|---|--|--|
| Product Weight Unboxed | Without Stand 13.29 lbs. 6.03kg | Adjustable Height Stand 19.24 lbs. 8.73kg | Recline Stand 21.12lbs 9.58kg |
| Shipping Weight Boxed | Without Stand 20.64-21.15lbs 9.4-9.45kg | Adjustable Height Stand 26.68 lbs. 12.1kg | Recline Stand 28.66-28.88 lbs. 13-13.1kg |
| Shipping Weight Pallet | Without Stand (10units) 233.73lbs 106kg | Adjustable Height Stand (10units) 293.21lbs 133 kg | Recline Stand (10units) 313.06lbs 142kg |

Weight without Touch Panel

| | | | |
|-------------------------------|---|--|--|
| Product Weight Unboxed | Without Stand 13.51-13.62 lbs. 6.13-6.18kg | Adjustable Height Stand 19.46-19.68lbs 8.93 kg | Recline Stand 21.34-21.44 lbs. 9.68-9.73kg |
| Shipping Weight Boxed | Without Stand 20.86-21.06lbs 9.5-9.55kg | Adjustable Height Stand 26.89-27.12 lbs. 12.2-12.3 kg | Recline Stand 28.88lbs 13.1kg |
| Shipping Weight Pallet | Without Stand 21.2 x 2.12 x 13.46 in 539.6 x 53.8 x 341.79 mm | Adjustable Height Stand 0 degrees 21.2 x 7.1 x 18.4 in 539.6 x 180.28 x 467.7 mm | Recline Stand 0 degrees 21.2 x 10.3 x 10.63 in 539.6 x 261.8 x 269.98 mm |

Technical Specifications

Dimensions (W x D x H)

| Product Dimensions | Without Stand | Adjustable Height Stand 0 degrees | Recline Stand 0 degrees |
|--------------------|--|---|---|
| | 21.2 x 2.12 x 13.46 in 539.6 x 53.8 x 341.79 mm | 21.2 x 7.1 x 18.4 in 539.6 x 180.28 x 467.7 mm | 21.2 x 10.3 x 10.63 in 539.6 x 261.8 x 269.98 mm |

Shipping Dimensions

| Shipping Dimensions Boxed | Without Stand | Adjustable Height Stand | Recline Stand |
|----------------------------|--|--|--|
| | 27.17 x 10.08 x 21.46(H) in 690 x 256 x 545(H) mm | 27.17 x 10.08 x 26.22(H) in 690 x 256 x 666(H) mm | 27.17 x 10.08 x 26.22(H) in 690 x 256 x 666(H) mm |
| Shipping Dimensions Pallet | Without Stand (10 units) | Adjustable Height Stand (10 units) | Recline Stand (10 units) |
| | 47.24 x 39.37 x 24.02(H) in 1200 x 1000 x 610(H) mm | 47.24 x 39.37 x 28.94(H) in 1200 x 1000 x 735(H) mm | 47.24 x 39.37 x 28.94(H) in 1200 x 1000 x 735(H) mm |

Technical Specifications – Miscellaneous Features

MISCELLANEOUS FEATURES

Management Features

- Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode. Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
- Intel® Wired for Management support; industry wide initiative to make Intel® architecture based PCs, servers and mobile computers more inherently manageable out-of-the-box and over the network
- Dual State Power Button; acts as both an on/off button and a suspend-to-sleep button

Serviceability Features

- Dual colored power LED on front of computer to indicate either normal or fault condition
- Diagnostic LED Explanation Table:
 - Power LED will blink red 2 to 5 times, then blink white 2 or more times, then repeat (with beep tones for each blink initially):
 - 2 red + 2 white User must provide file for BIOS recovery (USB storage typically)
 - 2 red + 3 white User must enter a key sequence to proceed with recovery by policy
 - 2 red + 4 white BIOS recovery is in progress
 - 3 red + 2 white Memory could not be initialized
 - 3 red + 3 white Graphics adaptor could not be found
 - 3 red + 4 white Power supply failure / not connected
 - 3 red + 5 white Processor not installed
 - 3 red + 6 white Current processor does not support an enabled feature
 - 4 red + 2 white Processor has exceeded its temperature threshold / system thermal shutdown
 - 4 red + 3 white System internal temperature has exceeded its threshold
 - 5 red + 2 white System controller firmware is not valid
 - 5 red + 3 white System controller detected BIOS is not executing
 - 5 red + 4 white BIOS could not complete initialization / PCA failure
 - 5 red + 5 white System controller rebooted the system after a health or recovery timer triggered
- HP PC Hardware Diagnostics UEFI:
 - This utility enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing F2 at POST, and is available as a download from HP Support
- System/Emergency ROM
- Flash ROM
- CMOS Battery Holder for easy replacement
- Flash Recovery with Video Configuration Record Software
- 5 Aux Power LED on System PCA
- Processor ZIF Socket for easy Upgrade
- Over-Temp Warning on Screen (Requires IM Agents)
- Clear Password Jumper
- DIMM Connectors for easy Upgrade
- Clear CMOS Button
- NIC LEDs (integrated) (Green & Amber)
- Dual Color Power and HD LED - To Indicate Normal Operations and Fault Conditions
- Color coordinated cables and connectors
- Tool-less Hood Removal
- Front power switch
- System memory can be upgraded without removing the system board or any internal components
- Tool-less Hard Drive, CD & Diskette Removal (For MT, SFF, and DM only)
- Green Pull Tabs, and Quick Release Latches for easy Identification

Technical Specifications – Miscellaneous Features

Additional Features

Tower Orientation

Description

Product can be oriented as either a desktop (horizontal) or a tower (vertical) for MT, SFF, and DM only

Drive Lock

Implementation of the industry standard ATA Security feature set. When enabled, it prevents software access to user data on the drive until one or two user-defined passwords are provided.

Boot Sectors Protection

MBR and GPT sectors of the hard drive are critical to booting the operating system. By saving the MBR or GPT data (depending on the how the OS was installed), the BIOS will be able to monitor for changes and allow the user to override them with the backup copy at boot-up.

Drive Protection System

DPS Access through F10 Setup during Boot

A diagnostic hard drive self- test. It scans critical physical components and every sector of the hard drive for physical faults and then reports any faults to the user

Running independently of the operating system, it can be accessed through a Windows-based diagnostics utility or through the computer's setup procedure. It produces an evaluation on whether the hard drive is the source of the problem and needs to be replaced

The system expands on the Self-Monitoring, Analysis, and Reporting Technology (SMART), a continuously running systems diagnostic that alerts the user to certain types of failures

SMART Technology (Self-Monitoring, Analysis and Reporting Technology)

Allows hard drives to monitor their own health and to raise flags if imminent failures were predicted

SMART I - Drive Failure Prediction

Predicts failures before they occur. Tracks fault prediction and failure indication parameters such as re-allocated sector count, spin retry count, calibration retry count

SMART II - Off-Line Data Collection

By avoiding actual hard drive failures, SMART hard drives act as "insurance" against unplanned user downtime and potential data loss from hard drive failure

SMART III - Off-Line Read Scanning with Defect Reallocation

IOEDC: I/O Error Detection Circuitry

SMART IV - End-to-End CRC for hard drives

Detects errors in Read/Write buffers on HDD cache RAM

Technical Specifications – After Market Options

AFTER MARKET OPTIONS

| Graphics Solutions | DM | SFF | TWR | AiO | Part Number |
|--|-----------|------------|------------|------------|--------------------|
| AMD® Radeon™ RX 550 4GB 2DP Card | | | X | | 3TK71AA |
| AMD® Radeon™ R7 430 2GB 2DP Card | | X | X | | 3MQ82AA |
| HP DisplayPort To HDMI True 4k Adapter | X | X | X | X | 2JA63AA |
| HP DVI Cable Kit | X | X | X | X | DC198A |
| HP HDMI Standard Cable Kit | X | X | X | X | T6F94AA |
| HP DisplayPort Cable Kit | X | X | X | X | VN567AA |
| HP DisplayPort To VGA Adapter | X | X | X | X | AS615AA |
| HP DisplayPort To DVI-D Adapter | X | X | X | X | FH973AA |

| Desktop Mini Accessories | DM | Part Number |
|---|---|--------------------|
| HP Desktop Mini G4 Port Cover Kit | X (95W and discrete GPU skus not supported) | 1ZE52AA |
| HP G4 Mini 2.5-inch SATA Drive Bay Kit | X (95W and discrete GPU skus not supported, cannot use in conjunction with Thunderbolt 3 and Fiber NIC) | 3TK91AA |
| HP Desktop Mini LockBox V2 | X (95W and discrete GPU skus not supported) | 3EJ57AA |
| HP Desktop Mini 500GB HDD/I/O Expansion Module | X (Either one) | K9Q82AA |
| HP Desktop Mini DVD-Writer ODD Expansion Module | | K9Q83AA |
| HP Desktop Mini I/O Expansion Module | | K9Q84AA |
| HP Desktop Mini Security/Dual VESA Sleeve v2 | X (95W and discrete GPU skus not supported) | 2JA32AA |
| HP Desktop Mini Vertical Chassis Stand | X | G1K23AA |
| HP DM VESA Power Supply Holder Kit | X (95W and discrete GPU skus not supported) *Must use with Dual VESA Sleeve V2 | 1RL87AA |

| Data Storage Drives | DM | SFF | TWR | AiO | Part Number |
|--|---|------------|------------|------------|--------------------|
| HP 256GB SATA TLC Non-SED Solid State Drive | X (95W and discrete GPU skus not supported, cannot use in conjunction with Thunderbolt 3 and Fiber NIC) | X | X | X | P1N68AA |
| HP PCIe NVME TLC 256GB SSD M.2 Drive | X | X | X | X | 1CA51AA |
| HP PCIe NVME TLC 512GB SSD M.2 Drive | X | X | X | X | X8U75AA |
| HP PCIe NVME TLC 512GB SSD PCIe Drive | | X | X | | Z4L70AA |
| HP 500GB 7200PRM SATA 6.0Gb/s 3.5" Hard Drive | | X | X | | QK554AA |
| HP 1TB 7200rpm SATA 6Gb/s 3.5" Hard Drive | | X | X | | QK555AA |
| HP SATA SuperMulti JB Drive | | | X | | QS208AA |
| HP 9.5mm Slim Removable SATA 500GB | | X | X | X | T7G14AA |
| HP 9.5mm G4 8/6/4 SFF G4 400 SFF/MT DVD Writer | | X | | | 1CA53AA |

Technical Specifications – After Market Options

| Input Devices | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> | <u>Part Number</u> |
|--|------------------|-------------------|-------------------|-------------------|---------------------------|
| HP USB (Grey) SmartCard CCID Keyboard | | X | X | | J7H70AA |
| HP USB Antimicrobial Business Slim Keyboard and Mouse (China Only) | | X | X | X | Z9H50AA |
| HP USB Business Slim CCID SmartCard Keyboard | X | X | X | X | Z9H48AA |
| HP USB Business Slim (Grey) Keyboard (EMEA Only) | X | X | X | X | Z9H49AA |
| HP USB Business Slim Keyboard | X | X | X | X | N3R87AA |
| HP USB Business Slim Keyboard and Mouse and Mousepad | | X | X | X | T4E63AA |
| HP USB Collaboration Keyboard | X | X | X | | Z9N38AA |
| HP USB Conferencing Keyboard | | | | X | K8P74AA |
| HP USB Keyboard | X | X | X | X | QY776AA |
| HP USB Keyboard and Mouse Healthcare Edition | X | X | X | X | 1VD81AA |
| HP USB Premium Keyboard | X | X | X | X | Z9N40AA |
| HP USB PS/2 Washable Keyboard & Mouse | X | X | X | X | BU207AA |
| HP Wireless Business Slim Keyboard and Mouse | X | X | X | X | N3R88AA |
| HP Wireless Collaboration Keyboard | X | X | X | | Z9N39AA |
| HP Wireless Premium Keyboard | | X | X | X | Z9N41AA |
| HP PS/2 Business Slim Keyboard | | X | X | | N3R86AA |
| HP USB Grey v2 Mouse (EMEA only) | X | X | X | X | Z9H74AA |
| HP USB Premium Mouse | X | X | X | X | 1JR32AA |
| HP PS/2 Mouse | | X | X | | QY775AA |
| HP USB 1000dpi Laser Mouse | X | X | X | X | QY778AA |
| HP USB Hardened Mouse | X | X | X | X | P1N77AA |
| HP USB Mouse | X | X | X | X | QY777AA |

Technical Specifications – After Market Options

| System Memory | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> | <u>Part Number</u> |
|--------------------------|-----------|------------|------------|------------|--------------------|
| HP 4GB DDR4-2666 DIMM | | X | X | | 3TK85AA |
| HP 8GB DDR4-2666 DIMM | | X | X | | 3TK87AA |
| HP 16GB DDR4-2666 DIMM | | X | X | | 3TK83AA |
| HP 4GB DDR4-2666 SODIMM | X | | | X | 3TK86AA |
| HP 8GB DDR4-2666 SODIMM | X | | | X | 3TK88AA |
| HP 16GB DDR4-2666 SODIMM | X | | | X | 3TK84AA |

| Multimedia Devices | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> | <u>Part Number</u> |
|-----------------------------|-----------|------------|------------|------------|--------------------|
| HP Business Headset v2 | X | X | X | X | T4E61AA |
| HP USB Business Speakers v2 | X | X | X | | N3R89AA |

| Security Devices | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> | <u>Part Number</u> |
|--------------------------------------|-----------|------------|------------|------------|--------------------|
| HP Solenoid Lock & Hood Sensor (SFF) | | X | | | 1CA50AA |
| HP Solenoid Lock & Hood Sensor (MT) | | | X | | J6L42AA |
| HP Business PC Security Lock v3 Kit | | X | X | | 3XJ17AA |
| HP Dual Head Keyed Cable Lock | | X | X | | T1A64AA |
| HP Keyed Cable Lock 10mm | X | X | X | X | T1A62AA |
| HP Master Keyed Cable Lock 10mm | | X | X | X | T1A63AA |

| Stands and Accessories | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> | <u>Part Number</u> |
|--|---|------------|------------|------------|--------------------|
| HP B300 PC Mounting Bracket | X | | | | 2DW53AA |
| HP B500 PC Mounting Bracket | X | | | | 2DW52AA |
| HP Single Monitor Arm | x (95W and discrete GPU skus not supported) | | | X | BT861AA |
| HP 800 G4/G4 AiO Adjustable Height Stand | | | | X | Z9H66AA |
| HP 800 G4/G4 AiO Recline Stand | | | | X | Z9H67AA |

Technical Specifications – After Market Options

| I/O Devices | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> | <u>Part Number</u> |
|--|---|-------------------|-------------------|-------------------|---------------------------|
| HP DisplayPort Port Flex IO | x (discrete GPU skus not supported) | X | X | | 3TK72AA |
| HP Fiber NIC Port Flex IO | x (95W and discrete GPU skus not supported) | | | | 3TK73AA |
| HP HDMI Port Flex IO (400/600/800) | x (discrete GPU skus not supported) | X | X | | 3TK74AA |
| HP Thunderbolt 3.0 Port Flex IO | x (95W and discrete GPU skus not supported) | | | | 3TK77AA |
| HP Thunderbolt 3.0 PCIe Card | | X | X | | 4CX35AA |
| HP Type-C™ USB 3.1 Gen2 Port Flex IO | x (discrete GPU skus not supported) | X | X | | 3TK78AA |
| HP Type-C™ USB 3.1 Gen2 Port with PD Flex IO | x (65W & 95W and discrete GPU skus not supported) | | | | 3TK79AA |
| HP VGA Port Flex IO | x (discrete GPU skus not supported) | X | X | | 3TK80AA |
| HP Serial Port Flex IO | x (discrete GPU skus not supported) | | | | 3TK76AA |
| HP Internal Serial Port (600/705/800) | | X | X | | 3TK82AA |
| HP PCIe x1 Parallel Port Card | | X | X | | N1M40AA |
| HP 800/600/400 G4 Serial/ PS/2 Adapter | | X | X | | 1VD82AA |

| Communication Devices | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> | <u>Part Number</u> |
|---|------------------|-------------------|-------------------|-------------------|---------------------------|
| Intel® 9260 802.11ac non-vPro™ PCIe x1 Card | | X | X | | 3TK89AA |
| Realtek 8822BE 802.11ac PCIe x1 Card | | X | X | | 3TK90AA |

| Intel® Optane Memory | <u>DM</u> | <u>SFF</u> | <u>TWR</u> | <u>AiO</u> | <u>Part Number</u> |
|-----------------------------------|------------------|-------------------|-------------------|-------------------|---------------------------|
| Intel® Optane Memory 16GB (Cache) | X | X | X | X | 1WV97AA |

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Change Log

| Date | Version History | Action | Description of Change |
|--------------------|-----------------|--------|---|
| June 6, 2018 | From v1 to v2 | Add | Environmental section |
| June 15, 2018 | From v2 to v3 | Add | Adjustable Height and Recline Stand |
| June 19, 2018 | From v3 to v4 | Update | Environmental specs for micro tower business |
| June 19, 2018 | From v4 to v5 | Update | Environmental Tab for Non-Touch All-in-One Business PC and Touch All-in-One Business PC |
| June 20, 2018 | From v5 to v6 | Update | Environmental tabs |
| June 20, 2018 | From v6 to v7 | Update | Weights & Dimensions |
| July 19, 2018 | From v7 to v8 | Update | Note for SATA Drive Bracket added to Internal Ports section Refresh Rate added to Panel specs |
| August 2, 2018 | From v8 to v9 | Update | Palletization profile corrected for DM SFF Call out image changed USB sentence reduced in the call outs specs and rest of QS 2.5 SSHD corrected to include SFF and TWR |
| August 21, 2018 | From v9 to v10 | Update | Windows Home removed |
| August 24, 2018 | From v10 to v11 | Update | Intel® Core™ i7-8700 Processors corrected Windows Home returned back |
| August 30, 2018 | From v11 to v12 | Update | Environmental table for AiO GPU fixed |
| September 19, 2018 | From v12 to v13 | Update | NVIDIA GeForce GT730 2GB DP DVI PCIe x8 GFX added to Graphics section for MT and SFF. |
| September 27, 2018 | From v13 to v14 | Update | Rear I/O connector added to AMD Radeon RX 560 graphic card Last bullet added to “At a Glance” section |
| October 11, 2018 | From v14 to v15 | Update | Footnote 33 updated to Raid 1 configuration |
| November 2, 2018 | From v15 to v16 | Update | Note added to Optional Discrete Graphics Solutions |
| November 14, 2018 | From v16 to v17 | Update | Max. Resolution added to Intel® UHD Graphics and AMD Radeon™ 560 |
| December 10, 2018 | From v17 to v18 | Update | NVIDIA® Quadro P620 2GB Graphics Card added to Tower business Graphics sections |
| December 17, 2018 | From v18 to v19 | Update | AMD Radeon™ R7 430 Graphics 2GB GDDR5 64bit 2DP, AMD Radeon™ R7 430 Graphics 2GB GDDR5 64bit DP+VGA, AMD Radeon™ RX 580 Graphics 8GB GDDR5 and NVIDIA® GeForce® RTX 2080 8GB GDDR6_ Added to graphics |
| January 3, 2019 | From v19 to v20 | Update | Response Time specs added to DISPLAY PANEL SPECIFICATIONS |
| February 1, 2019 | From v20 to v21 | Update | HP PhoneWise, HP ePrinter + Jet advantage, HP Velocity, and HP WorkWise removed. |
| February 11, 2019 | From v21 to v22 | Update | Support for “VESA 100 mounting system on bottom of PC chassis” added to mounting in call outs section for DM |
| February 13, 2019 | From v22 to v23 | Update | I210 NIC switched to “Add-on” instead of “integrated” |
| February 27, 2019 | From v23 to v24 | Update | Typo corrected in the title: M.2 PCIe NVMe Solid State Drives (SSD) |
| March 6, 2019 | From v24 to v25 | Update | Type C port USB port (2.0 or 3.0) and PORTS information charging capability statement update and PORTS information, on USB type C port, (15W) added. |
| March 12, 2019 | From v25 to v26 | Update | Declared Noise Emissions values for EliteDesk 800 Small Form Factor G4 series updated |
| March 26, 2019 | From v26 to v27 | Update | HP Solenoid Lock & Hood Sensor (SFF) part number corrected in AMO section |